

STM32L4 and STM32L4+ Series to STM32U575/585 migration guide

Introduction

Designers of STM32 microcontroller applications must be able to easily replace one microcontroller type by another one in the same product family or products from a different family.

Migrating an application to a different microcontroller is often needed when product requirements grow, putting extra demands on memory size, or increasing the number of I/Os. The cost reduction objectives may also be an argument to switch to smaller components and shrink the PCB area.

This application note analyzes the steps required to migrate from an existing design on the STM32L4 or STM32L4+ Series to the STM32U575/585 line microcontrollers.

This document lists the full set of features available for STM32L4 and STM32L4+ Series, and the equivalent features of STM32U575/585, and provides a guideline on both hardware and peripheral migration.

To fully benefit from this application note, the user must be familiar with the STM32 microcontroller family. For additional information, refer to the product datasheets and reference manuals.



1 STM32U575/585 overview

The STM32U575/585 devices use a new technology compared to STM32L4 and STM32L4+ Series, achieving excellence in ultra-low-power with more security.

The STM32U575/585 enhance efficiency and performance with up to 2 Mbytes of Flash memory and up to 786 Kbytes of RAM.

These devices provide improved security features thanks to the ultra-low-power Arm®Cortex®-M33 32-bit core, with TrustZone® for Armv8-M and to the ST instruction cache (ICACHE), that supports both internal and external memories and a dedicated data cache (DCACHE) for external memories.

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1.1 Main features

The STM32U575/585 include a larger set of peripherals with more advanced features compared to the STM32L4 and STM32L4+, such as the ones listed below:

- Security
 - Arm TrustZone and securable I/Os, memories and peripherals
 - RDP and password protected debug, active tamper, secure firmware upgrade support, secure firmware installation, secure hide protection
 - Up to 8 configurable SAU regions
 - Additional encryption accelerator engine (available only on STM3U585xx devices)
 - HASH hardware accelerator
 - 2 advanced encryption hardware accelerators (AES) including one with DPA resistance
 - Public key accelerator (PKA), DPA resistant
 - On-the-fly decryption engine of OCTOSPI (OTFDEC)
- Power consumption
 - Embedded regulator (LDO)
 - SMPS step-down converter
 - Regulators are placed in parallel, thus it is possible to switch from one to another on the fly.
 - Both regulators can provide four different voltages (voltage scaling) and can operate in Stop modes.
 - Optimized RTC consumption
- Performance
 - Frequency up to 160 MHz
 - Direct access to Flash interface through ICACHE (without passing by AHB bus)
 - ICACHE for internal and external memories
 - DCACHE for external memories
- New peripherals
 - Advanced 14-bit ADC and ultra-low-power 12-bit ADC
 - Mathematics accelerators: FMAC and CORDIC
 - Digital filters: MDF and ADF

Note:

This document only manages the differences between the STM32L4, STM32L4+ Series and STM32U575/585 for the common features. The new features of STM32U575/585, mainly linked to the TrustZone support, are not covered. The detailed list of available features and packages for each product is available in the respective product datasheet.

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The table below summarizes the memory availability of the STM32U575/585.

Table 1. STM32U575/585 memory availability

Products	Flash men	iory		RAM size (Kbytes)			Feature level	
Fioducts	Size	Bank	SRAM1	SRAM2	SRAM3	SRAM4	BKPSRAM	reature lever
STM32U575xx	1 to 2 Mbytes							Without hardware crypto
STM32U585xx	2 Mbytes	Dual	192	64	512	16	2	With hardware crypto: AES, PKA, and OTFDEC

1.2 System architecture

The STM32U575/585 embed high-speed memories (2-Mbyte Flash memory and 786-Kbyte SRAM), a flexible external memory controller (FSMC) for static memories (available on high-pin-count packages: 100 pins and more), two Octo-SPI interface (available on all packages), and an extensive range of enhanced I/Os and peripherals connected to a 32-bit multi-AHB bus matrix, three AHB buses and three APB buses.

The following table illustrates the bus matrix differences between STM32L4, STM32L4+ and STM32U575/585.

Table 2. Bus matrix on STM32L4, STM32L4+ and STM32U575/585

Bus type	STM32L4	STM32L4+	STM32U575/585
AHB bus	5 masters:	Up to 9 masters:	Up to 11 masters:
matrix masters	CPU, AHB system, D-Code, I-Code, DMA1 and DMA2 ⁽¹⁾	CPU, AHB system, D-Code, I-Code, DMA1 and DMA2, DMA2D, LCD-TFT controller DMA, SDMMC1, SDMMC2, GFXMMU ⁽²⁾	Fast C-bus, Slow C-bus, CPU S-bus for internal memories, CPU S-bus for external memories, GPDMA1, DMA2D, SDMMC1, SDMMC2
AHB bus matrix slaves	Up to 8 slaves: internal Flash memory (on I-Code and D-Code bus), SRAM1, SRAM2, AHB1 (including APB1 and APB2), AHB2, FMC and QUADSPI	Up to 11 slaves: internal Flash memory (on I-Code and D-Code bus), SRAM1, SRAM2, SRAM3, GFXMMU, AHB1 (including APB1 and APB2), AHB2, OCTOSPI1, OCTOSPI2 and FSMC	Up to 10 slaves: internal Flash memory, SRAM1, SRAM2, SRAM3, AHB1 peripherals (including APB1 and APB2)and backup RAM, AHB2 peripherals, FSMC, OCTOSPI1, OCTOSPI2, SmartRun domain (SRD) peripherals and SRAM4

- 1. Up to six masters with DMA2D only for STM32L496/4A6xx.
- 2. SDMMC2 and GFXMMU only available for STM32L4P5/L4Q5xx.

The bus matrix provides access from a master to a slave, enabling concurrent access and efficient operation even when several high-speed peripherals work simultaneously.

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The system architectures of STM32L4, STM32L4+ and STM32U575/585 are shown in the figures below.

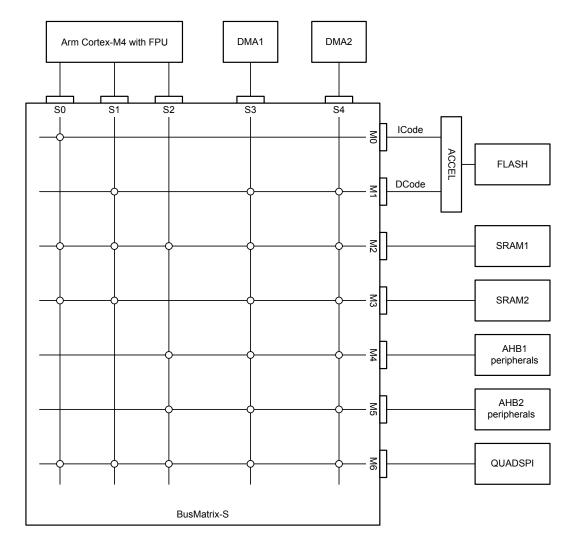


Figure 1. STM32L4 Series system architecture

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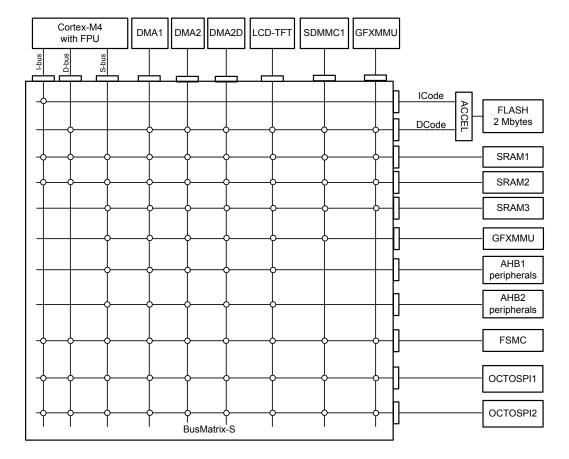


Figure 2. STM32L4+ Series system architecture

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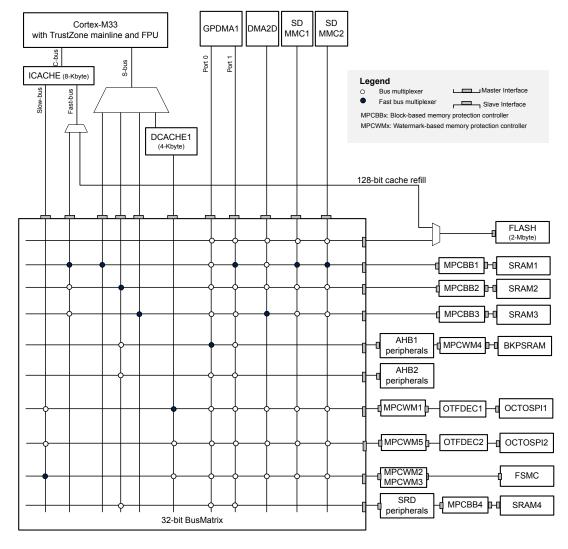


Figure 3. STM32U575/585 system architecture

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2 Hardware migration

The STM32U575/585 offer eight packages from 48 to 169 pins, and two pinout versions:

- without internal SMPS: most packages are compatible with STM32L4 and STM32L4+.
- with internal SMPS: fully new packages that are not compatible with STM32L4 and STM32L4+.
 For this pinout version, the SMPS step-down converter and the LDO are embedded in parallel to provide the V_{CORE} supply.

For more details on the pinout, refer to the product datasheets.

The table below lists the available packages on the STM32U575/585 compared to STM32L4 and STM32L4+, as well as their compatibility.

Table 3. Packages on STM32U575/585 compared to STM32L4 and STM32L4+

Package ⁽¹⁾ (Size in mm x mm)	STM32L4	STM32L4+	STM32U575/585	STM32U575/585 without SMPS compared to STM32L4/L4+	STM32U575/585 with SMPS compared to STM32L4/L4+
LQFP144 (20 x 20)	X ⁽²⁾⁽³⁾	X	X		
LQFP100 (14 x 14)	X ⁽⁶⁾	Х	X	Compatible ⁽⁴⁾	
LQFP64 (10 x 10)	Х	N/A	X		
UFBGA169 (7 x 7)	X ⁽⁷⁾	X	X	Incompatible	Now pipout/hallout(5)
UFBGA132 (7 x 7)	X ⁽³⁾	X	X	Incompatible	New pinout/ballout ⁽⁵⁾
LQFP48 (7 x 7)	X ⁽⁸⁾	N/A	X	Compatible(4)	
UFQFPN48 (7 x 7)	X ⁽⁹⁾	N/A	X	Compatible ⁽⁴⁾	
WLCSP90 (4.20 x 3.95)	N/A	N/A	X	N/A	

- 1. For more details about the available packages for STM32L4 and STM32L4+, refer to product datasheet.
- 2. X = available, N/A = not available
- 3. Available only for STM32L47/48/49/4Axxx.
- 4. Compatible except PB11 pin in STM32L4/L4+ that becomes VCAP on STM32U575/585.
- 5. Eight new packages introduced for STM3U575/585 with SMPS step-down converter option.
- 6. Not available for STM32L41/42xxx.
- 7. Available only for STM32L49/4Axxx.
- 8. Not available for STM32L45/46/47/48/49/4Axxx devices.
- 9. Not available for STM32L47/48/49/4Axxx devices.

When SMPS is supported, new dedicated pinout supporting the SMPS step-down converter are available for STM32U575/585.

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When SMPS is not supported, the STM32U575/585 are pin to pin compatible with the STM32L4 and STM32L4+ except:

- UFBGA132 and UFBGA169 packages: incompatible pinouts (refer to the product datasheet for the full pinout tables)
- for other packages, the only incompatibility is in PB11 pin in STM32L4 and STM32L4+, that is replaced by VCAP pin on STM32U575/585.

Table 4. PB11/VCAP pin position

Package	Only different pin	STM32L4 and STM32L4+	STM32U575/585	
LQFP144 (20 x 20)	70			
LQFP100 (14 x 14)	48			
LQFP64 (10 x 10)	30	PB11	VCAP	
LQFP48 (7 x 7)	22			
UFQFPN48 (7 x 7)	22			

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3 Boot mode compatibility

3.1 Boot mode selection

For the STM32U575/585, the BOOT0 input pin may come from the PH3-BOOT0 pin or from an option bit, depending on the value of a user option bit to free the GPIO pad if needed.

The tables below present the STM32U575/585 boot modes, when TrustZone is disabled or enabled.

Table 5. Boot modes when TrustZone is disabled (TZEN = 0)

nBOOT0 FLASH_ OPTR[27]	BOOT0 pin PH3	nSWBOOT0 FLASH_ OPTR[26]	Boot address option bytes selection	Boot area	ST programmed default value
-	0	1	NSBOOTADD0[24:0]	Boot address defined by user option bytes NSBOOTADD0[24:0]	Flash: 0x0800 0000
-	1	1	NSBOOTADD1[24:0]	Boot address defined by user option bytes NSBOOTADD1[24:0]	System bootloader: 0x0BF9 0000
1	-	0	NSBOOTADD0[24:0]	Boot address defined by user option bytes NSBOOTADD0[24:0]	Flash: 0x0800 0000
0	-	0	NSBOOTADD1[24:0]	Boot address defined by user option bytes NSBOOTADD1[24:0]	System bootloader: 0x0BF9 0000

Table 6. Boot modes when TrustZone is enabled (TZEN = 1)

BOOT _LOCK	nBOOT0 FLASH_ OPTR[27]	BOOT0 pin PH3	nSWBOOT0 FLASH_ OPTR[26]	RSS command	Boot address option- bytes selection	Boot area	ST programmed default value
	-	0	1	0	SECBOOTADD0[24:0]	Secure boot address defined by user option bytes SECBOOTADD0[24:0]	Flash: 0x0C00 0000
	-	1	1	0	N/A	RSS: 0x0FF8 0000	
0	1	-	0	0	SECBOOTADD0[24:0]	Secure boot address defined by user option bytes SECBOOTADD0[24:0]	Flash: 0x0C00 0000
	0	-	0	0	N/A	RSS: 0x0FF8 0000	
	-	-	-	≠0	IN/A	K33. 0x0FF6 0000	
1	-	-	-	-	SECBOOTADD0[24:0]	Secure boot address defined by user option bytes SECBOOTADD0[24:0]	Flash: 0x0C00 0000

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In STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx, the boot mode is selected with the nBOOT1 option bit and the BOOT0 pin, or nBOOT0 option bit, depending on the value of the nSWBOOT0 option bit in the FLASH_OPTR register (see the table below).

Table 7. Boot modes for STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx

nBOOT1 FLASH_ OPTR[23]	nBOOT0 FLASH_ OPTR [27]	BOOT0 pin PH3	nSWBOOT0 FLASH_ OPTR [26]	Main Flash empty	Boot memory space alias
X	X	0	1	0	Main Flash memory selected as boot area
X	X	0	1	1	System memory selected as boot area
X	1	X	0	X	Main Flash memory selected as boot area
0	X	1	1	Х	Embedded SRAM1 selected as boot area
0	0	Х	0	X	Embedded SRAM1 selected as boot area
1	Х	1	1	X	System memory selected as boot area
1	0	X	0	X	System memory selected as boot area

^{1.} X = equivalent to 0 or 1.

In the other STM32L4 devices (STM32L47/48xxx), the boot mode is selected with one BOOT0 pin and the nBOOT1 option bit located in the user option bytes, at memory address 0x1FFF 7800 (see the table below).

Table 8, Boot modes for STM32L47/48xxx

Selected boot area	BOOT1 ⁽¹⁾	воот0
Main Flash memory	X ⁽²⁾	0
System Flash memory	0	1
Embedded SRAM1	1	1

^{1.} The BOOT1 value is the opposite of the nBOOT1 option bit.

3.2 Embedded bootloader

The embedded bootloader is located in the system memory and programmed by ST during production. It allows the Flash memory to be reprogrammed, using the serial interfaces listed in the table below.

Table 9. Bootloader interface on STM32L4, STM32L4+ and STM32U575/585

Peripheral	Pin	STM32L4 and STM32L4+	STM32U575/585
DFU	USB_DM (PA11)	X	X
DFO	USB_DP (PA12)	X	X
USART1	USART1_TX (PA9)	X	Х
USARTI	USART1_RX (PA10)	X	X
USART2	USART2_TX (PA2)	X	X
USARTZ	USART2_RX (PA3)	X	X
USART3	USART3_TX (PC10)	X	X

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^{2.} For STM32L41/42/43/44/45/46xxx, a Flash memory empty check mechanism is implemented to force the boot from system Flash memory, if the first Flash memory location is not programmed (0xFFFF FFFF), and if the boot selection was configured to boot from the main Flash memory.

^{2.} X = equivalent to 0 or 1.



USART3 USART3_RX (PC11) X X I2C1 I2C1_SCL (PB6) X X I2C2 I2C1_SDA (PB7) X X I2C2 I2C2_SCL (PB10) X X I2C3 I2C2_SDA (PB11) X X I2C3 I2C3_SCL (PC0) X X I2C4 I2C4_SCL (PD12) X(1) NA I2C4 I2C4_SCL (PD12) X(1) NA I2C4 SCL (PD13) X(1) NA SP11_NSS (PA4) X X X SP11_SCK (PA5) X X X SP11_MISO (PA6) X X X SP11_MOSI (PA7) X X X SP12_NSS (PB12) X X X SP12_MISO (PB14) X X X SP12_MOSI (PB15) X X X SP13_MISO (PG10) NA X X SP13_MISO (PG10) NA X X SP13_MOSI (PB5)	Peripheral	Pin	STM32L4 and STM32L4+	STM32U575/585
12C1	USART3	USART3_RX (PC11)	Х	Х
12C1_SDA (PB7)	1204	I2C1_SCL (PB6)	X	X
I2C2	I2C1	I2C1_SDA (PB7)	Х	Х
I2C2_SDA (PB11) X	1202	I2C2_SCL (PB10)	Х	X
12C3	1202	I2C2_SDA (PB11)	X	X
I2C3_SDA (PC1)	1000	I2C3_SCL (PC0)	X	X
SPI1_NSS (PA4)	1203	I2C3_SDA (PC1)	X	X
SPI1_NSS (PA4) X X X X X X X X X	1004	I2C4_SCL (PD12)	X ⁽¹⁾	NA
SPI1_SCK (PA5) X X SPI1_MISO (PA6) X X SPI1_MOSI (PA7) X X SPI2_NSS (PB12) X X SPI2_NSS (PB12) X X SPI2_SCK (PB13) X X SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(4) NA	1204	I2C4_SDA (PD13)	X ⁽¹⁾	NA
SPI1 SPI1_MISO (PA6) X X SPI1_MOSI (PA7) X X SPI2_NSS (PB12) X X SPI2_SCK (PB13) X X SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN2_RX (PB5) X(4) NA		SPI1_NSS (PA4)	X	Х
SPI1_MISO (PA6) X X SPI1_MOSI (PA7) X X SPI2_NSS (PB12) X X SPI2_SCK (PB13) X X SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN2_RX (PB5) X(4) NA	0.014	SPI1_SCK (PA5)	X	Х
SPI2_NSS (PB12) X X SPI2_SCK (PB13) X X SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA	SPI1	SPI1_MISO (PA6)	X	Х
SPI2 SPI2_SCK (PB13) X X SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA		SPI1_MOSI (PA7)	X	Х
SPI2 SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA		SPI2_NSS (PB12)	X	Х
SPI2_MISO (PB14) X X SPI2_MOSI (PB15) X X SPI3_NSS (PG12) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA	ODIO	SPI2_SCK (PB13)	X	Х
SPI3_NSS (PG12) SPI3_NSS (PG9) NA X SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA	SPIZ	SPI2_MISO (PB14)	X	Х
SPI3 SPI3_SCK (PG9) NA X SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA		SPI2_MOSI (PB15)	X	Х
SPI3 SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA		SPI3_NSS (PG12)	NA	X
SPI3_MISO (PG10) NA X SPI3_MOSI (PB5) NA X CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA	ODIO	SPI3_SCK (PG9)	NA	Х
CAN1_RX (PB8) X(2) X(3) CAN1_TX (PB9) X(2) X(3) CAN2_RX (PB5) X(4) NA	SPI3 -	SPI3_MISO (PG10)	NA	X
CAN1		SPI3_MOSI (PB5)	NA	Х
CAN1_TX (PB9) X ⁽²⁾ X ⁽³⁾ CAN2_RX (PB5) X ⁽⁴⁾ NA	CANG	CAN1_RX (PB8)	X ⁽²⁾	X ⁽³⁾
CAN2 CAN2_RX (PB5) X ⁽⁴⁾ NA	CAN1	CAN1_TX (PB9)	X ⁽²⁾	X ⁽³⁾
CAN2		CAN2_RX (PB5)	X ⁽⁴⁾	NA
CAN2_TX (PB6) X ⁽⁴⁾ NA	CAN2	CAN2_TX (PB6)	X ⁽⁴⁾	NA

- 1. Only for STM32L45/46/49/4Axxx.
- 2. Not available on STM32L41/42xxx.
- 3. FDCAN1 is available for STM32U575/585.
- 4. Only for STM32L49/4Axxx.

For more details on the bootloader, refer to the application note *STM32 microcontroller system memory boot mode* (AN2606).

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4 Peripheral migration

4.1 Cross-compatibility between STM32 products

STM32 microcontrollers embed a set of peripherals that can be classified in the following groups:

- Group1: peripherals by definition common to all products
 - Those peripherals are identical, so they have the same structure, registers and control bits. There is no need to perform any firmware change to keep the same functionality at the application level after migration. All the features and behavior remain the same.
- Group2: peripherals shared by all products but with only minor differences (in general to support new features)
 - The migration from one product to another is very easy and does not need any significant new development effort.
- Group3: peripherals that have considerable changes from one product to another (new architecture or new features for example)

For this group of peripherals, the migration requires a new development at application level.

For STM32U575/585, each GPIO or peripheral, DMA channel, clock configuration register, ICACHE, DCACHE or small part of Flash memory or SRAM, can be configured as trusted or untrusted. The following table summarizes the available peripherals in STM32L4 and STM32L4+, compared to STM32U575/585, as well as their compatibility.

Table 10. STM32 peripheral compatibility between STM32L4, STM32L4+ and STM32U575/585

Peripheral		STM32L4	STM32L4+	STM32U575/585	
Core		Cortex-M4		Cortex-M33	
Maximum CPU	frequency	Up to 80 MHz	120 MHz	160 MHz	
Power supply			1.71 V to 3.6 V with V _{BAT}		
Elh	Size	1 Mbytes	2 M	bytes	
Flash memory	Bank		Dual bank	Dual or single bank with TrustZone	
	SRAM1	Up to 256 Kbytes	192 k	Kbytes	
SRAMs	SRAM2	Up to 64 Kbytes	64 K	bytes	
SKAIVIS	SRAM3	N/A	384 Kbytes	512 Kbytes	
	SRAM4	N/A	N/A	16 Kbytes	
DMA		DMA request line is connected directly to peripherals.	DMA request line is connected to peripherals through DMAMUX.	 GPDMA request line is connected to peripherals through the integrated multiplexor. LPDMA request line is connected to peripherals through the integrated multiplexor. 	
		2			
DMAMUX		N/A	Yes	N/A	
DMA2D		N/A ⁽¹⁾	Y	´es	
GPDMA			N/A	Yes	
LPDMA			N/A	Tes	
FSMC (external memory controller for static memory)		Yes			
QUADSPI		Yes	N	I/A	

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Peripheral		STM32L4	STM32L4+	STM32U575/585			
OCTOSPI		N/A	2	1			
LCD		Yes ⁽²⁾	√ √A				
SWPMI		Yes	1	N/A			
LTDC		N/A	Yes	N/A			
DCMI		N/A ⁽³⁾	,	Yes			
	Advanced control		2 (16-bit)				
	Conord numero		5 (16-bit)	3 (16-bit)			
	General purpose		2 (32-bit)	4 (32-bit)			
Timoro	Basic		2 (16-bit)				
Timers	Low power		2 (16-bit)	4 (16-bit)			
	SysTick		1	2			
	IWDG		1				
	WWDG		1				
	SPI	3 ⁽⁴⁾		3			
	I2C	3 ⁽⁵⁾		4			
	USART		3				
	UART	2					
	LPUART	1					
Communication	SAI	2					
interfaces	CAN		1	1x FDCAN			
	USB	OTG_FS without clock recovery ⁽⁶⁾	OTG_FS with	ith clock recovery			
		FS device interface ⁽⁷⁾ N/A					
	UCPD (USB Power Delivery)		N/A	Yes			
	SDMMC	1 ⁽⁸⁾	2 ⁽⁹⁾	2			
RTC			Yes				
GFXMMU		N/A	Yes	N/A			
Tamper pins			Up to 3	Up to 8 (7 active)			
Random generat	tor		Yes				
GPIOs ⁽¹⁰⁾		Up to 114	Up to 140	Up to 137			
Wakeup pins			Up to 5	Up to 24 (multiplexed on 8 events)			
Number of I/Os down to 1.08 V		Up to 14					
Capacitive sensi	ng channels	Up to 24					
DFSDM (digital filters for sigma-delta modulators)			Yes	N/A			
ADF			Yes				
MDF			N/A	Yes ⁽¹¹⁾			
14-bit ADC	Instance		N/A	1			
14-DIL ADC	Number of channels		IN/ <i>P</i> 1	Up to 20			
12-bit ADC	Instance	3 ⁽¹²⁾	1	1			

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Peripheral		STM32L4 STM32L4+		STM32U575/585		
12-bit ADC	Number of channels		Up to 19	Up to 24		
12-bit DAC	Instance		2	·		
Internal voltage reference buffer		Yes				
Analog compa	rator (COMP)	2				
Operational an	nplifiers (OPAMP)	2 ⁽¹³⁾ 2				
EXTI		Yes				
PWR		Yes				
SYSCFG		Yes				
DSI		N/A	Yes N/A			
HASH		N/A ⁽³⁾	Yes			
AES		Yes ⁽¹⁴⁾	Yes			
PKA		N/A Yes ⁽¹⁶⁾		Yes ⁽¹⁵⁾		
OTFDEC (on-the-fly decryption)		N/A				

- 1. Only available on STM32L496/4A6xx.
- 2. Not available on STM32L4x1.
- 3. Only available on STM32L496/4A6xx.
- 4. Only two on STM32L41/42xxx.
- 5. Four on STM32L452/462/496/4A6xx.
- 6. Only on STM32L47/48/49/4Axxx.
- 7. Only on STM32L41/42/43/44/45/46xxx.
- 8. Not available on STM32L41x/42x/432/442xx devices.
- 9. Only available on STM32L4P5/Q5xx devices.
- 10. If an SMPS package type is used for STM32L4 and STM32L4+, two GPIOs are replaced by VDD12 pins, to connect the SMPS power supplies, hence reducing the number of available GPIOs by two.
- 11. DFSDM is replaced by MDF in STM32U575/585.
- 12. Only two on STM32L41/42xx and only one on STM32L43/44/45/46xx.
- 13. Only one on STM32L41/42/43/44/45/46xxx.
- 14. Not available for STM32L476/486xx.
- 15. AES, PKA and OTFDEC are available only on STM32U585xx.
- 16. Only available on STM32L4P5/Q5xx.

4.2 Memory mapping

The peripheral address mapping has been changed in the STM32U75/585 compared to the STM32L4 and STM32L4+, as shown in the table below (see the product datasheet for more details).

Table 11. Peripheral address mapping of STM32L4, STM32L4+ and STM32U575/585

	Bus	STM32L4/L4+	Bus	STM32U575/585	
Peripheral		Boundary address ⁽¹⁾		Secure boundary address	Non-secure boundary address
HASH		0x5006 0400- 0x5006 07FF	AHB2	0x520C 0400- 0x520C 07FF	0x420C 0400- 0x420C 07FF
AES		0x5006 0000- 0x5006 03FF		0x520C 0000- 0x520C 03FF	0x420C 0000- 0x420C 03FF
DCMI	AHB2	0x5005 0000- 0x5005 03FF		0x5202 C000- 0x5202 C3FF	0x4202 C000- 0x4202 C3FF
GPIOI		0x4800 2000- 0x4800 23FF		0x5202 2000- 0x5202 23FF	0x4202 2000- 0x4202 23FF
OCTOSPIM		0x5006 1C00- 0x5006 1FFF		0x520C 4000- 0x520C 43FF	0x420C 4000- 0x420C 43FF

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		STM32L4/L4+		STM32U575/585	
Peripheral	Bus	Boundary address ⁽¹⁾	Bus	Secure boundary address	Non-secure boundary address
DMA2D		0x4002 B000- 0x4002 BBFF	AHB1	0x5002 B000- 0x5002 BBFF	0x4002 B000- 0x4002 BBFF
GFXMMU ⁽²⁾	AHB1	0x4002 C000- 0x4002 EFFF		NI/A	
DMAMUX1		0x4002 0800- 0x4002 0BFF	N/A		
I2C4	APB1	0x4000 8400- 0x4000 87FF	APB1	0x5000 8400- 0x5000 87FF	0x4000 8400- 0x4000 87FF
OCTOSPI2	NI/A	0xA000 1400- 0xA000 17FF		0x520D 2400- 0x520D 27FF	0x420D 2400- 0x420D 27FF
OCTOSPI1	N/A	0xA000 1000- 0xA000 13FF	AHB2	0x520D 1400- 0x520D 17FF	0x420D 1400- 0x420D 17FF
FSMC	AHB3 ⁽³⁾	0xA000 0000- 0xA000 03FF		0x520D 0400- 0x520D 07FF	0x420D 0400- 0x420D 07FF
DSI	ADDO	0x4001 6C00- 0x4001 73FF			
LTDC	APB2	0x4001 6800- 0x4001 6BFF		N/A	
UCPD1		N/A	APB1	0x5000 DC00- 0x5000 DFFF	0x4000 DC00- 0x4000 DFFF
USB SRAM	1004	0x4000 6C00- 0x4000 6FFF		N/A	
USB FS	APB1	0x4000 6800- 0x4000 6BFF		N/A	
OTG_FS	AHB2	0x5000 0000- 0x5003 FFFF		0x5203 8000- 0x520B FFFF	0x4203 8000- 0x420B FFFF
SDMMC1	APB2/ AHB2	 0x4001 2800- 0x4001 2BFF (APB2) on STM32L4 0x5006 2400- 0x5006 27FF (AHB2) on STM32L4+ 		0x520C 8000- 0x520C 83FF	0x420C 8000- 0x420C 83FF
SDMMC2	AHB2	0x5006 2800- 0x5006 2BFF ⁽²⁾		0x520C 8C00- 0x520C 8FFF	0x420C 8C00- 0x420C 8FFF
OTFDEC1				0x520C 5000- 0x520C 53FF	0x420C 5000- 0x420C 53FF
OTFDEC2		N/A		0x520C 5400- 0x520C 57FF	0x420C 5400- 0x420C 57FF
PKA		0x5005 E000- 0x5005 FFFF ⁽²⁾		0x520C 2000- 0x520C 3FFF	0x420C 2000- 0x420C 3FFF
PSSI		0x5005 0400- 0x5005 07FF ⁽²⁾		0x5202 C400- 0x5202 C7FF	0x4202 C400- 0x4202 C7FF
RNG		0x5006 0800- 0x5006 0BFF	-	0x520C 0800- 0x520C 0BFF	0x420C 0800- 0x420C 0BFF
ADC1 ⁽⁴⁾				0x5202 8000- 0x5202 83FF	0x4202 8000- 0x4202 83FF
ADC2 (5)		0x5004 0000- 0x5004 03FF	AHB3	0x5602 1000- 0x5602 13FF	0x4602 1000- 0x4602 13FF
GPIOH		0x4800 1C00- 0x4800 1FFF		0x5202 1C00- 0x5202 1FFF	0x4202 1C00- 0x4202 1FFF
GPIOG	AHB2	0x4800 1800- 0x4800 1BFF	-	0x5202 1800- 0x5202 1BFF	0x4202 1800- 0x4202 1BFF
GPIOF		0x4800 1400- 0x4800 17FF	-	0x5202 1400- 0x5202 17FF	0x4202 1400- 0x4202 17FF
GPIOE		0x4800 1000- 0x4800 13FF	ALIBO	0x5202 1000- 0x5202 13FF	0x4202 1000- 0x4202 13FF
GPIOD		0x4800 0C00- 0x4800 0FFF	AHB2	0x5202 0C00 - 0x5202 0FFF	0x4202 0C00- 0x4202 0FFF
GPIOC		0x4800 0800- 0x4800 0BFF	-	0x5202 0800- 0x5202 0BFF	0x4202 0800- 0x4202 0BFF
GPIOB		0x4800 0400- 0x4800 07FF		0x5202 0400- 0x5202 07FF	0x4202 0400- 0x4202 07FF
GPIOA		0x4800 0000- 0x4800 03FF	-	0x5202 0000- 0x5202 03FF	0x4202 0000- 0x4202 03FF
GTZC1_TZSC				0x5003 2400- 0x5003 27FF	0x4003 2400- 0x4003 27FF
GTZC1_TZIC	N/A			0x5003 2800- 0x5003 2BFF	0x4003 2800- 0x4003 2BFF
GTZC1_ MPCBB1			AHB1	0x5003 2C00- 0x5003 2FFF	0x4003 2C00- 0x4003 2FFF
GTZC1_ MPCBB2			AIIDI	0x5003 3000- 0x5003 33FF	0x4003 3000- 0x4003 33FF
GTZC1_ MPCBB3				0x5003 3400- 0x5003 37FF	0x4003 3400- 0x4003 37FF

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		STM32L4/L4+		STM32U575/585		
Peripheral	Bus	Boundary address ⁽¹⁾	Bus	Secure boundary address	Non-secure boundary address	
TSC		0x4002 4000- 0x4002 43FF		0x5002 4000- 0x5002 43FF	0x4002 4000- 0x4002 43FF	
CRC		0x4002 3000- 0x4002 33FF	AHB1	0x5002 3000- 0x5002 33FF	0x4002 3000- 0x4002 33FF	
Flash registers	ALID4	0x4002 2000- 0x4002 23FF		0x5002 2000- 0x5002 23FF	0x4002 2000- 0x4002 23FF	
RCC	AHB1	0x4002 1000- 0x4002 13FF	AHB3	0x5602 0C00- 0x5602 0FFF	0x4602 0C00- 0x4602 0FFF	
DMA1		0x4002 0000- 0x4002 03FF		NI/A		
DMA2		0x4002 0400- 0x4002 07FF	N/A			
GPDMA1		N/A	AHB1	0x5002 0000- 0x5002 0FFF	0x4002 0000- 0x4002 0FFF	
LPDMA1		IN/A	AHB3	0x5602 5000- 0x5602 5FFF	0x4602 5000- 0x4602 5FFF	
FIREWALL		0x4001 1C00- 0x4001 1FFF		NA		
EXTI		0x4001 0400- 0x4001 07FF	AHB3	0x5602 2000- 0x5602 23FF	0x4602 2000- 0x4602 23FF	
DFSDM1		0x4001 6000- 0x4001 67FF		N/A		
SAI2		0x4001 5800- 0x4001 5BFF		0x5001 5800- 0x5001 5BFF	0x4001 5800- 0x4001 5BFF	
SAI1		0x4001 5400- 0x4001 57FF		0x5001 5400- 0x5001 57FF	0x4001 5400- 0x4001 57FF	
TIM17		0x4001 4800- 0x4001 4BFF		0x5001 4800- 0x5001 4BFF	0x4001 4800- 0x4001 4BFF	
TIM16		0x4001 4400- 0x4001 47FF		0x5001 4400- 0x5001 47FF	0x4001 4400- 0x4001 47FF	
TIM15	APB2	0x4001 4000- 0x4001 43FF	APB2	0x5001 4000- 0x5001 43FF	0x4001 4000- 0x4001 43FF	
USART1		0x4001 3800- 0x4001 3BFF		0x5001 3800- 0x5001 3BFF	0x4001 3800- 0x4001 3BFF	
TIM8	-	0x4001 3400- 0x4001 37FF		0x5001 3400- 0x5001 37FF	0x4001 3400- 0x4001 37FF	
SPI1	-	0x4001 3000 - 0x4001 33FF		0x5001 3000- 0x5001 33FF	0x4001 3000- 0x4001 33FF	
TIM1		0x4001 2C00- 0x4001 2FFF		0x5001 2C00- 0x5001 2FFF	0x4001 2C00- 0x4001 2FFF	
COMP		0x4001 0200- 0x4001 03FF		0x5600 5400- 0x5600 57FF	0x4600 5400- 0x4600 57FF	
VREFBUF		0x4001 0030- 0x4001 01FF	APB3	0x4600 5400- 0x4600 57FF	0x4600 7400- 0x4600 77FF	
SYSCFG		0x4001 0000 - 0x4001 002F		0x5600 0400- 0x5600 07FF	0x4600 0400- 0x4600 07FF	
FDCAN1 RAM		A.I/A	APB1	0x5000 AC00- 0x5000 AFFF	0x4000 AC00- 0x4000 AFFF	
LPTIM3		N/A	APB3	0x5600 4800- 0x5600 4BFF	0x4600 4800- 0x4600 4BFF	
CAN1/ FDCAN1 ⁽⁶⁾		0x4000 6400- 0x4000 67FF	APB1	0x5000 A400- 0x5000 A7FF	0x4000 A400- 0x4000 A7FF	
LPTIM2		0x4000 9400- 0x4000 97FF	APB2	0x5000 9400- 0x5000 97FF	0x4000 9400- 0x4000 97FF	
LPUART1		0x4000 8000- 0x4000 83FF		0x5600 2400- 0x5600 27FF	0x4600 2400- 0x4600 27FF	
LPTIM1		0x4000 7C00- 0x4000 7FFF	APB3	0x5600 4400- 0x5600 47FF	0x4600 4400- 0x4600 47FF	
OPAMP		0x4000 7800- 0x4000 7BFF		0x5600 5000- 0x5600 53FF	0x4600 5000- 0x4600 53FF	
DAC ⁽⁷⁾		0x4000 7400- 0x4000 77FF	ALIDO	0x5602 1800- 0x5602 1BFF	0x4602 1800- 0x4602 1BFF	
PWR	APB1	0x4000 7000- 0x4000 73FF	— AHB3	0x5602 0800- 0x5602 0BFF	0x4602 0800- 0x4602 0BFF	
CRS		0x4000 6000- 0x4000 63FF	APB1	0x5000 6000- 0x5000 63FF	0x4000 6000- 0x4000 63FF	
I2C3	-	0x4000 5C00- 0x4000 5FFF	APB3	0x5600 2800- 0x5600 2BFF	0x4600 2800- 0x4600 2BFF	
I2C2	-	0x4000 5800- 0x4000 5BFF		0x5000 5800- 0x5000 5BFF	0x4000 5800- 0x4000 5BFF	
I2C1	-	0x4000 5400- 0x4000 57FF		0x5000 5400- 0x5000 57FF	0x4000 5400- 0x4000 57FF	
UART5	-	0x4000 5000- 0x4000 53FF	APB1	0x5000 5000- 0x5000 53FF	0x4000 5000- 0x4000 53FF	
UART4	-	0x4000 4C00- 0x4000 4FFF		0x5000 4C00- 0x5000 4FFF	0x4000 4C00- 0x4000 4FFF	

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		STM32L4/L4+		STM32U575/585	
Peripheral	Bus	Boundary address ⁽¹⁾	Bus	Secure boundary address	Non-secure boundary address
USART3		0x4000 4800- 0x4000 4BFF	APB1	0x5000 4800- 0x5000 4BFF	0x4000 4800- 0x4000 4BFF
USART2		0x4000 4400- 0x4000 47FF	AIDI	0x5000 4400- 0x5000 47FF	0x4000 4400- 0x4000 47FF
SPI3		0x4000 3C00- 0x4000 3FFF	APB3	0x5600 2000- 0x5600 23FF	0x4600 2000- 0x4600 23FF
SPI2		0x4000 3800- 0x4000 3BFF		0x5000 3800- 0x5000 3BFF	0x4000 3800- 0x4000 3BFF
TAMPER and BKP registers ⁽⁸⁾		0x4000 3400- 0x4000 37FF ⁽⁹⁾	APB1	0x5600 7C00- 0x5600 7FFF	0x4600 7C00- 0x4600 7FFF
IWDG		0x4000 3000- 0x4000 33FF		0x5000 3000- 0x5000 33FF	0x4000 3000- 0x4000 33FF
WWDG	APB1	0x4000 2C00- 0x4000 2FFF		0x5000 2C00- 0x5000 2FFF	0x4000 2C00- 0x4000 2FFF
RTC		0x4000 2800- 0x4000 2BFF	APB3	0x5600 7800- 0x5600 7BFF	0x4600 7800- 0x4600 7BFF
TIM7		0x4000 1400- 0x4000 17FF		0x5000 1400- 0x5000 17FF	0x4000 1400- 0x4000 17FF
TIM6		0x4000 1000- 0x4000 13FF		0x5000 1000- 0x5000 13FF	0x4000 1000- 0x4000 13FF
TIM5		0x4000 0C00- 0x4000 0FFF	APB1	0x5000 0C00- 0x5000 0FFF	0x4000 0C00- 0x4000 0FFF
TIM4		0x4000 0800- 0x4000 0BFF		0x5000 0800- 0x5000 0BFF	0x4000 0800- 0x4000 0BFF
TIM3		0x4000 0400- 0x4000 07FF		0x5000 0400- 0x5000 07FF	0x4000 0400- 0x4000 07FF
TIM2		0x4000 0000- 0x4000 03FF		0x5000 0000- 0x5000 03FF	0x4000 0000- 0x4000 03FF
ADF1			AHB3	0x5602 4000- 0x5602 4FFF	0x4602 4000- 0x4602 4FFF
LPGPIO1	-			0x5602 0000- 0x5602 03FF	0x4602 0000- 0x4602 03FF
LPTIM4			APB3	0x5600 4C00- 0x5600 4FFF	0x4600 4C00- 0x4600 4FFF
DLYBOS1				0x520C F000- 0x520C F3FF	0x420C F000- 0x420C F3FF
DLYBOS2				0x520C F400- 0x520C F7FF	0x420C F400- 0x420C F7FF
DLYBSD1			AHB2	0x520C 8400- 0x520C 87FF	0x420C 8400- 0x420C 87FF
DLYBSD2				0x520C 8800- 0x520C 8BFF	0x420C 8800- 0x420C 8BFF
SAES		N/A		0x520C 0C00- 0x520C 0FFF	0x420C 0C00- 0x420C 0FFF
BKPSRAM				0x5003 6400- 0x5003 6BFF	0x4003 6400- 0x4003 6BFF
DCACHE				0x5003 1400 - 0x5003 17FF	0x4003 1400 - 0x4003 17FF
ICACHE				0x5003 0400- 0x5003 07FF	0x4003 0400- 0x4003 07FF
RAMCFG			AHB1	0x5002 6000- 0x5002 6FFF	0x4002 6000- 0x4002 6FFF
MDF1				0x5002 5000- 0x5002 5FFF	0x4002 5000- 0x4002 5FFF
FMAC				0x5002 1400- 0x5002 17FF	0x4002 1400- 0x4002 17FF
CORDIC				0x5002 1000- 0x5002 13FF	0x4002 1000- 0x4002 13FF

- 1. If no boundary address, it means the peripheral is not available on all STM32L4/L4+.
- 2. Only available on STM32L4P5/4Q5xx.
- 3. AHB4 for STM32L49/4Axxx.
- 4. ADC1 for STM32U575/585. ADC1 and ADC2 for STM32L4P/4Q5xx.
- 5. Named ADC4 for STM32U575/585.
- 6. FDCAN1 for STM32U575/585.
- 7. DAC1 for STM32L4+ and STM32U575/585.
- 8. TAMP for STM32U575/585.
- 9. Only on STM32L4+.

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4.3 System peripherals

4.3.1 System configuration controller (SYSCFG)

Table 12. SYSCFG features of STM32L4, STM32L4+ and STM32U575/585

STM32L4/L4+	STM32U575/585
 Remapping memory areas Managing the external interrupt line connection to the GPIOs Managing robustness feature Setting SRAM2 write protection and software erase Configuring FPU interrupts Enabling the firewall Enabling/disabling the I2C Fast-mode plus driving capability on some I/Os 	 Managing robustness feature Setting SRMA2 write protection and software erase: this feature is not ensured by SYSCFG peripheral but using RAMCFG peripheral. Configuring FPU interrupts Enabling/disabling the I2C fast-mode plus driving capability on some I/Os and voltage booster for I/Os analog switches Configuring TrustZone security register access Tracking the PVT conditions to control the current slew-rate and output impedance in I/O buffer through compensations cells on VDD and VDDIO2

4.3.2 Embedded Flash memory (FLASH)

Table 13. FLASH features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585
Page size	 0x0800 0000 to up to 0x080F FFFF 0x0810 0000 to up to 0x081F FFFF (only for STM32L4+) 	 Bank1: 0x0800 0000 to 0x080F FFFF Bank2: 0x0810 0000 to 0x081F FFFF
Main/program memory	For STM32L4+: up to 2 Mbytes split in two banks when dual bank is enabled: each bank = 256 pages of 4 Kbytes each page = 8 rows of 512 bytes when dual bank is disabled: memory block contains 256 pages of 8 Kbytes each page = 8 rows of 1024 bytes For STM32L47/48/49/4Axxx: up to 1 Mbyte split in two banks: each bank = 256 pages of 2 Kbytes each page = 8 rows of 256 bytes For STM32L45/46xxx: up to 512 Kbytes one bank each bank = 256 pages of 2 Kbytes each page = 8 rows of 256 bytes For STM32L43/44xxx: up to 256 Kbytes one bank each bank = 128 pages of 2 Kbytes each page = 8 rows of 256 bytes	 up to 2 Mbytes: dual-bank architecture 1 Mbyte per bank for main memory 8 Kbytes page size system memory: 32 Kbytes 32 Kbytes immutable secure area containing the root security services

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Feature		STM32L4/L4+	STM32U575/585
		For STM32L41/42xxx: up to 128 Kbytes one bank = 64 pages of 2 Kbytes	
Specific features		RWW (read-while-write) dual-bank boot (only for STM32L4+ and STM32L47/48/49/4Axxx)	RWW (read-while-write)dual-bank boot
ECC (single-double-error	error correction and detection)	Programming and read granularity: 72 bits (including 8 ECC bits)	128 effective bits plus 9 ECC bits
Read access	S	Read access of 64 bits	128-bit wide data read
Wait states (WS)	Up to 4 WS (depending on the supply voltage and the frequency)	 The number of WS depends on LPM value: Up to 4 WS when LPM = 0 (depending on the supply voltage and the frequency) Up to 16 WS when LPM = 1 (depending on the supply voltage and the frequency)
One time pro	ogrammable (OTP)	1-Kbyte OTP bytes (bank1)	512-byte OTP for user data
	Level 0 (RDP = 0xAA)	No protection : No debug restriction	Device open No debug restriction (secure and non-secure) Boot @ must target a secure area. Boot on secure SRAM, Flash memory and system Flash (RSS) possible
Read protection (RDP)	Level 0.5 (RDP = 0x55)	N/A	Device partially closed (only when TrustZone is enabled) Non-secure debug only NS-Flash access allowed (with debug connection) Boot @ must target secure user Flash memory. Boot on SRAM not permitted Regression from Level 1 to level 0.5 can be blocked by OEM2 key.
	Level 1 (RDP ≠ {0xAA,0xCC})	Memory readout protection	Device memories protected: Flash, backup registers, SRAM2 and backup RAM totally inaccessible: Non-secure debug only Flash access not allowed (with debug connection) Boot @ must target secure user Flash memory. Regression from Level 1 to level 0 can be blocked by OEM1 key.
	Level 2 (RDP = 0xCC)	Full protection: No debug ⁽¹⁾	 Closed device (no JTAG) No option byte change: No debug (JTAG fuse) Boot @ in secure user Flash memory RDP level 2 cannot be changed, unless OEM2 unlocking key is activated.
Write protection (WRP)		Two write protection area per bank: 2-Kbyte granularity For STM32L4+ Series: dual bank with 2 areas per bank or single bank with 4 areas	Two write protection area per bank: 8-Kbyte granularity

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	Feature	STM32L4/L4+	STM32U575/585
	RDP option bytes	0xAA: Level 00xCC: Level 2Others: Level 1	 0xAA: Level 0 0x55: Level 0.5 0xCC: Level 2 Others: Level 1
	Reset option bytes	 BOR_LEV[2:0] nRST_STOP nRST_STDBY nRST_SHDW SRAM134_RST (only on STM32U575/585) SRAM2_RST 	
	Watchdog option bytes	IDWG_SWIWDG_STOPIWDG_STDBYWWDG_SW	
		BFB2 (except for STM32L41/42/43/44/45/46xxx)	SWAP_BANK
	FLASH banking option bytes	 Dual bank (except for STM32L4+ Series and STM32L41/42/43/44/45/46xxx) DB1M (for STM32L4+ Series) DBANK (for STM32L4+ Series) 	DUALBANK
User option bytes	RAM and ECC enable option bits	N/A (parity check option bit only)	BKPRAM_ECCSRAM3_ECCSRAM2_ECC
Dylos		SRAM2_PE	Removed, replaced by ECC options bits
	Secure and non-secure boot option bytes	nSWBOOT0 (only for STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx)	nSWBOOT0
		nBOOT0 (only for STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx)	nBOOT0
			NSBOOTADD0[24:0]NSBOOTADD1[24:0]SECBOOTADD0[24:0]
	IO speed and pull-up selection option bits	N/A	PA15_PUPENIO_VDD_HSLVIO_VDDIO2_HSLV
	Global TrustZone activation option bit		TZEN
	FLASH secure watermark option bytes	For STM32L4 Series: PCROPx_STRT[15:0] PCROPx_END[15:0] For STM32L4+ Series: PCROPx_STRT[16:0] PCROPx_END[16:0]	 SECWM1_PSTRT[6:0] ECWM1_PEND[6:0] HDP1_PEND[6:0] HDP1EN SECWM2_PSTRT[6:0] SECWM2_PEND[6:0] HDP2_PEND[6:0] HDP2EN

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	Feature	STM32L4/L4+	STM32U575/585
User option bytes	FLASH write protection (WRP) area option bytes FLASH locking keys for level regression option bytes	N/A	 WRP1A_PSTRT[6:0] WRP1A_PEND[6:0] WRP1B_PSTRT[6:0] WRP1B_PEND[6:0] WRP2A_PSTRT[6:0] WRP2A_PEND[6:0] WRP2B_PSTRT[6:0] WRP2B_PEND[6:0] UNLOCK OEM1KEY[31:0] OEM2KEY[31:0] OEM2KEY[63:32] OEM2KEY[63:32]
Protections		 Write protection: 2 areas per bank PCROP protection: one PCROP area per bank 	 4 write protection areas: 2 per bank Configurable protection against unprivileged accesses with Flash page granularity
Security		N/A	 TrustZone 2 secure areas (1 per bank) 2 secure HDP (hide protection) areas part of the secure areas (1 per bank)

Memory read protection Level 2 is an irreversible operation. When Level 2 is activated, the level of protection cannot be decreased to Level 0 or Level 1.

4.3.3 SRAMs

In STM32L4 and STM32L4+, the control of SRAM1 and SRAM2 is integrated within the SYSCFG. However, in STM32U575/585, a new peripheral, RAMCFG controller, is dedicated to control SRAM1, SRAM2, SRAM3, SRAM4 and BKPSRAM. Refer to section 'RAMs configuration controller' in the product reference manual for more details.

Table 14. SRAM features of STM32L4, STM32L4+ and STM32U575/585

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Feature		STM32L4	STM32L4+	STM32U575/585		
CPU	System bus	SRAM1	SRAM1, SRAM2, SRAM3	SRAM1, SRAM2, SRAM3, SRAM4 and BKPSRAM		
access bus	Other bus access	SRAM1, SRAM2 (I-bus/D-bus)	SRAM1, SRAM2, SRAM3 (C-bus)			
		SRAM1, SRAM2 and all registers content are retained in Stop 0, Stop 1 and Stop 2 modes.	SRAM1, SRAM2, SRAM3 and all registers content are retained in Stop 0, Stop 1 and Stop 2 modes.	Either 8 Kbytes, 56 Kbytes or 64 Kbytes of SRAM2 can be retained in Standby mode		
Retention		N	/A	BKPSRAM: Retention in Standby mode Optional retention in V _{BAT} mode		
Security		N	N/A			
Hardware erase conditions		N	 All SRAMs are erased by hardware in case of RDP level regression to L0.5 or L0. SRAM2 and optionally BKPSRAM are protected by the tamper detection circuit, and are erased by hardware in case of tamper detection. SRAM2 and BKPSRAM are erased by hardware in case of a Backup domain reset. 			
Software eraconditions	ase	The SRAM2 erase can also be reques in SYSCFG_SCSR.	All SRAMs erase can be requested by executing a specific software sequence, detailed in section 'RAMCFG' of the product reference manual.			
		The SRAM2 can be erased with a system reset using the option bit SRAM2_RST in the Flash memory user option bytes.				
System rese	et erase	N	SRAM1, SRAM3 and SRAM4 are erased when a system reset occurs if the SRAM134_RST option bit is selected in the Flash memory user option bytes.			
		SRAM2 can be write-protected with a page granularity of 1 Kbyte.				
WRP		The write protection can be enabled in register (SYSCFG_SWPR).	Each 1-Kbyte page can be write-protected by setting its corresponding PxWP (x = 0 to 63) bit in RAMCFG registers.			
		Single-error correction and double-error detection				
				ECC: 7 bits added per 32 bits		
Error detect	ion and	Parity check: 4 bits added per 32 bits (ECC enabled by user option bytes (see section 'Flash memory' of the product reference manual)			
correction		Parity check supported by the SRAM2	only	ECC supported by SRAM2, SRAM3 and BKPSRAM		
		If one parity bit fails, an NMI is general	ted.	Interrupts are generated when single- and/or double-ECC errors are detected:		

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Feature	STM32L4	STM32U575/585	
Error detection and correction	Event can be linked to the BRK_IN bre or TIM17.	2 ECC RAMCFG interrupts 1 ECC NMI interrupt Interrupts allow the device to exit Sleep, Stop 0 or Stop 1 mode, but not Standby mode.	
Read access latency	N.	/A	3-bit programmable wait-states depending on AHB clock frequency (HCLK) and voltage scaling range (for all SRAMs)

4.3.4 Instruction and data caches (ICACHE/DCACHE)

The STM32U575/585 embed an ICACHE (8 Kbytes) and a DCACHE1 (4 Kbytes) that allows more efficient use of the external memory through OCTOSPI and FSMC ports.

The STM32L4 and STM32L4+ Series do not embed these caches.

4.3.5 Direct memory access controller (DMA)

The STM32L4, STM32L4+ and STM32U575/585 have different DMA architecture and features.

All devices embed two DMA controllers:

- DMA1 (7 channels) and DMA2 (7 channels) for STM32L4 and STM32L4+
- GPDMA1 (16 channels) and LPDMA1 (4 channels) for STM32U575/585

STM32U575/585 and STM32L4+ embed also a Chrom-ART Accelerator (DMA2D) that is a specialized DMA dedicated to image manipulation. DMA2D peripheral is not present in STM32L4. The following table illustrates the main differences between DMA requests in STM32L4, STM32L4+ and STM32U575/585.

Table 15. DMA features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32	L4/L4+	STM32U575/585			
reature	DMA1	DMA2	GPDMA1	LPDMA1		
Architecture		Each instance of DI	MA controllers can access memory and peripherals.			
Number of instances	1	1	1	1		
Number of masters	1 single bidirection insta	al AHB master per ance	Dual bidirectional AHB master	Single bidirectional AHB master		
Number of channels	7	7	16	4		
Linked-List	N.	/A	 Separately programmed source and destination transfers Programmable data handling between source and destination Block-level (programmable number of data bytes) Linear source and destination addressing: programmable signed address offsets between successive burst transfers 			
Linked-List 2D addressing	N/A		 2D source and destination addressing Scatter-gather (multi-buffer transfers), data interleaving and de-interleaving via 2D addressing 			
N/A Autonomous data transfer in		Autonomous data transfers and wakeu power mode				
Sleep and Stop modes	N/A		Sleep, Stop 0 and Stop 1 modes	Sleep, Stop 0, Stop 1 and Stop 2 modes		
TrustZone security	N/A		Yes			
Privileged/unprivileged DMA	N/A		Yes			

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4.3.6 Reset and clock control (RCC)

The STM32U575/585 implement the same RCC features than the STM32L4 and STM32L4+, but with some specification updates.

Table 16. RCC features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585				
MSI	 MSI is a low-power oscillator with programmable frequency up to 48 MHz. It can replace PPLs as system clock (faster wakeup, lower consumption). It can be used as USB device clock (no need for external high speed crystal oscillator). 12 frequency ranges are available: 100 kHz, 200 kHz, 400 kHz, 800 kHz, 1 MHz, 2 MHz, 4 MHz (default value), 8 MHz, 16 MHz, 24 MHz, 32 MHz and 48 MHz. Auto-calibration from LSE 	 MSI is made of four internal RC oscillators. Two output clocks are generated from these divided oscillators: MSIS and MSIK. MSIS can replace PPLs as system clock (faster wakeup, lower consumption). MSIK can be selected by some peripherals as kernel clock. MSI can be used as USB device clock (no need for external high-speed crystal oscillator). 16 frequency ranges are available (from 100 kHz to 48 MHz). Refer to "MSIS and MSIK ranges per internal MSIRCs" table on the reference manual for more information. Default value for MSIS and MSIK frequencies is 4 MHz. Auto-calibration from LSE 				
HSI16	16 MHz RC factory and user trimmed					
LSI	 32 kHz RC Lower consumption, higher accuracy (refer to the experiment) 	electrical characteristics section of the datasheet)				
HSE	4 to 48 MHz	4 to 50 MHz				
LSE	 32.768 kHz Configurable drive/consumption Available in Backup domain (VBAT) 					
HSI48	 48 MHz RC (only for STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx) Can drive USB FS, SDMMC and RNG 	48 MHz RCCan drive USB FS, SDMMC and RNG				
SHSI	N/A	Internal securable RC oscillator dedicated to clock the SAES				
PLL	Main PLL for system: - x2 PLLs for SAI1/2, ADC, RNG, SDMMC and OTG_FS clock (for STM32L4+ and STM32L47/48/49/4Axxx) - x1 PLL for SAI1, ADC, RNG, SDMMC, USB FS clock (for STM32L43/44/45/46xxx) Each PLL provides up to three independent outputs. The PLL sources are MSI, HSI16, HSE.	Three PLLs: Main PLL(PLL1) provides clock for CPU and some peripherals. PLL2 and PLL3 generate the kernel clocks for peripherals. Each PLL offers three independent outputs with post-dividers. The internal PLLs can be used to multiply the HSI16, HSE or MSIS output clock frequency. Capability to work in integer or fractional mode				
System clock frequency	Up to 80 MHz (or 120 for STM32L4+)4 MHz after reset using MSI	Maximum frequency is 160 MHz.4 MHz after reset using MSI				
AHB, APB1, APB2 frequency	Up to 80 MHz (or 120 for STM32L4+) Up to 160 MHz					
RTC clock source	LSI, LSE or HSE/32					

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Feature	STM32L4/L4+	STM32U575/585
MCO clock source	MCO pin (PA8): SYSCLK, HSI16, HSE, PLLCLK, MSI, LSE, LSI or HSI48 (for STM32L4+ and STM32L41/42/43/44/45/46/49/4Axxx) With configurable prescaler 1, 2, 4, 8 or 16 for each output	One of nine clock signals can be selected as MCO clock: LSI, LSE, SYSCLK, HSI16, HSI48, HSE, PLLCLK, MSIS or MSIK.
Clock security system (CSS)	CSS on HSE or CSS on LSE	
Internal oscillator measurement/calibration	 LSE connected to TIM15 or TIM16 CH1: can measure HSI16 or MSI with respect to LSE clock high precision. LSI connected to TIM16 CH1: can measure LSI with respect to HSI16 or HSE clock precision. HSE/32 connected to TIM17 CH1: can measure HSE with respect to LSE/HSI16 clock. MSI connected to TIM17 CH1: can measure MSI with respect to HSI16/HSE clock. On STM32L41/42/43/44/45/46xxx, the HSE/32 and MSI are connected to TIM16 CH1. 	The frequency of all on-board clock sources can be indirectly measured by mean of the TIM15, TIM16 or TIM17 channel 1 input capture and LPTIM1 or LPTIM2 channel 2 input capture. Calibration using LSE: HSI16 and MSI calibration using LSE and TIM15/TIM16/TIM17 and LPTIM2. Calibration using HSE: HSI16 and MSI calibration using HSE, TIM16/TIM17 and LPTIM2 LSI calibration using HSE, TIM16/TIM17 and LPTIM1
Interrupt	CSS (linked to NMI IRQ) LSECSS, LSIRDY, LSERDY, HSIRDY, MSIRDY, HSERDY, PLLRDY, PLLSAI1RDY, PLLSAI2RDY (only on STM32L4+ and STM32L47/48/49/4Axxx) (linked to RCC global IRQ)	CSS (linked to NMI IRQ) HSECSS, HSERDY, LSERDY, HSIRDY, SHSIRDY, HSI48RDY, LSIRDY, MSISRDY, MSIKRDY, PLL1RDY, PLL2RDY, PLL3RDY, ITAMP3
Autonomous mode	N/A	 Peripherals supporting autonomous mode are able to generate a kernel clock and AHB/APB bus clock requests when needed even in Stop mode. Either MSI or HSI16 are woken up for this purpose.

4.3.6.1 Performance versus VCORE ranges

In STM32U575/585, the maximum CPU clock frequency and the number of Flash memory wait states depend on the selected voltage range V_{CORE} . The tables below present the different clock source frequencies depending on different product voltage range for STM32L4, STM32L4+ and STM32U575/585.

Table 17. RCC registers of STM32L4 and STM32L4+

CPU	Power	rmance V _{CORE}	Typical			Max freque	ncy (MHz) ⁽²⁾		
performance performa			value (V)	5 WS	4 WS	3 WS	2 WS	1 WS	0 WS
				STM32L4	Series				
High	Medium	1	1.2	-	80	64	48	32	16
Medium	High	2	1.0	-	26	26	18	12	6
				STM32L4+	Series				
High	Medium	1 (boost mode)	1.28	120	100	80	60	40	20
nign Medium	IVICUIUIII	1 (normal mode)	1.2	-	-	80	60	40	20
Medium	High	2	1.0	-	-	-	26	16	8

^{1.} When power performance increases, power consumption per MHz decreases.

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^{2.} WS = wait states.



Table 18. RCC registers of STM32U575/585

CPU	Power		Typical	Max frequency (MHz)											
perform	perform	V _{CORE} range	value			LPN	1 = 0					LPN	1 = 1		
ance	ance		(V)	5 WS	4 WS	3 WS	2 WS	1 WS	0 WS	5 WS	4 WS	3 WS	2 WS	1 WS	0 WS
High	Low	1	1.2	-	160	128	96	64	32	Up to 16 WS may be needed to obtain max clock source when LPM = 1 for ranges 1,2 and 3. Refer to FLASH section, table "Number of wait					
Medium - high	Medium - low	2	1.1	-	-	100	75	50	25					wait	
Medium - low	Medium - high	3	1.0	-	-	50	37.5	25	12.5	states according to CPU clock (HCLK) frequency (LPM = 1)" in the reference manual for more information.					
Low	High	4	0.9	-	-	-	24	16	8	-	-	-	24	16	8

4.3.6.2 Peripheral access configuration

Since the address mapping of some peripherals has been changed in the STM32U575/585 compared to STM32L4 and STM32L4+, different registers must be used to [enable/disable] or [enter/exit] the peripheral [clock] or [from Reset mode]. In addition, the STM32U575/585 need to [enable/disable] the autonomous mode for SmartRun domain (SRD). The table below shows the RCC registers used for peripheral access configuration in STM32L4, STM32L4+ and STM32U575/585.

Table 19. RCC registers for peripheral access configuration of STM32L4, STM32L4+ and STM32U575/585

Bus	STM32L4/L4+	STM32U575/585	Comments
АНВ	RCC_AHB1RSTR (AHB1)RCC_AHB2RSTR (AHB2)	 RCC_AHB1RSTR (AHB1) RCC_AHB2RSTR (AHB2) RCC_AHB3RSTR (AHB3) RCC_AHB4RSTR (AHB4) 	Used to [enter/exit] the AHB peripheral from reset
APB1	RCC_AHB1ENR (AHB1)RCC_AHB2ENR (AHB2)	 RCC_AHB1ENR (AHB1) RCC_AHB2ENR (AHB2) RCC_AHB3ENR (AHB3) RCC_AHB4ENR (AHB4) 	Used to [enable/disable] the AHB peripheral clock
APB2	 RCC_AHB1SMENR (AHB1) RCC_AHB2SMENR (AHB2) RCC_AHB3SMENR (AHB3) 	 RCC_AHB1SMENR (AHB1) RCC_AHB2SMENR (AHB2) RCC_AHB3SMENR (AHB3) RCC_AHB4SMENR (AHB4) 	Used to [enable/disable] the AHB peripheral clock in Sleep mode
		RCC_APB3RSTR	Used to [enter/exit] the APB3 peripheral from reset
APB3	N/A	RCC_APB3ENR	Used to [enable/disable] the APB1 peripheral clock
	IN/A	RCC_APB3SMENR	Used to [enable/disable] the APB1 peripheral clock in Sleep mode
SRD (SmartRun domain)		RCC_SRDAMR	Used to [enable/disable] the peripheral in autonomous mode in Stop 0,1,2 modes

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4.3.6.3 Peripheral clock configuration

The peripherals presented below have a dedicated clock source (independent from the system clock), that is used to generate the clock required for their operation. This section presents the difference between STM32L4, STM32L4+ and STM32U575/585, for the peripherals with different clock sources.

SAI

- In STM32L4+ and STM32L47/48/49/4Axxx devices, the SAI clocks are derived from one of the following sources:
 - an external clock mapped on SAI1_EXTCLK or SAI2_EXTCLK
 - PLLSAI1 VCO (PLLSAI1CLK)
 - PLLSAI2 VCO (PLLSAI2CLK)
 - main PLL VCO (PLLSAI3CLK)
 - HSI16 clock
- In STM32L43/44/45/46xxx devices, the SAI clocks are derived from one of the following sources:
 - an external clock mapped on SAI1_EXTCLK for SAI1
 - PLLSAI1 (P) divider output (PLLSAI1CLK)
 - main PLL (P) divider output (PLLSAI2CLK)
 - HSI16 clock
- In STM32U575/585 devices, the SAI1 and SAI2 clocks are derived from one of the following sources (selected by software):
 - an external clock mapped on AUDIOCLK for SAI1 and SAI2
 - PLL1_p clock
 - PLL2_p clock
 - PLL3 p clock
 - HSI16 clock

DFSDM/ADF/MDF

- In STM32L4 and STM32L4+ devices, the DFSDM clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - APB2 clock (PCLK2)
- In STM32U575/585 devices, the MDF and ADF audio clocks are derived from one of the following sources (selected by software):
 - PLL1 _p clock
 - PLL3_q clock
 - MSIK clock

OCTOSPI

- STM32L4 devices do not support the OCTOSPI peripheral.
- In STM32L4+ devices, the OCTOSPI clock is derived from one of the following sources (selected by software):
 - system clock
 - PLL48M1CLK
 - MSI clock
- In STM32U575/585 devices, the OCTOSPI clock is derived from one of the following sources (selected by software):
 - system clock
 - PLL1 q clock
 - MSIK clock
 - PLL2 q clock

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FDCAN

In STM32U575/585 devices, the FDCAN clock is derived from one of the following sources (selected by software):

- PLL1_q clock
- PLL2 p clock
- HSE clock

Note: FDCAN is not available on STM32L4 and STM32L4+ devices.

OTG_FS

- In STM32L4 and STM32L4+ devices, the OTG_FS clock is derived from one of the following sources (selected by software):
 - main PLL VCO (PLL48M1CLK)
 - PLLSAI1 VCO (PLL48M2CLK)
 - MSI clock (only when auto-trimmed with the LSE)
 - HSI48 internal oscillator (not available on STM32L4x1/475/476/486xx)
- In STM32U575/585 devices, the OTG_FS clock is derived from one of the following sources (selected by software):
 - PLL1_q clock
 - PLL2 q clock
 - HSI48 clock
 - MSIK clock

SDMMC

- In STM32L4 and STM32L4+ devices, the SDMMC clock is derived from one of the following sources (selected by software):
 - PLL1 p clock
 - PLLSAI1 VCO (PLL48M2CLK)
 - MSI clock (only when auto-trimmed with the LSE)
 - HSI48 internal oscillator (not available on STM32L4x1/475/476/486xx)
- In STM32U575/585 devices, the SDMMC clock is derived from one of the following sources (selected by software):
 - PLL1 p clock
 - CLK48 (48 MHz)

RNG

- In STM32L4 and STM32L4+ devices, the RNG clock is derived from one of the following sources (selected by software):
 - PLL1_p clock
 - PLLSAI1 VCO (PLL48M2CLK)
 - MSI clock (only when auto-trimmed with the LSE)
 - HSI48 internal oscillator (not available on STM32L4x1/475/476/486xx)
- In STM32U575/585 devices, the RNG clock is derived from one of the following sources (selected by software):
 - PLL1_p clock
 - HSI48 internal oscillator

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ADC/DAC

- In STM32L4 and STM32L4+ devices, the ADC clock is derived from one of the following sources (selected by software):
 - System clock (SYSCLK)
 - PLLSAI1 VCO (PLLADC1CLK): not available on STM3L41/42xxx
 - PLLSAI2 VCO (PLLADC2CLK): not available on STM32L4+ and STM32L41/42/43/44/45/46xxx
- STM32L4 and STM32L4+ devices do not have a dedicated clock for DAC, independent from the system clock.
- In STM32U575/585 devices, the ADC and DAC clock is derived from one of the following sources (selected by software):
 - System clock (SYSCLK)
 - HCLK
 - pll2 r ck
 - HSE
 - HSI16
 - MSIK
 - LSI and LSE: only as DAC1 clock source

U(S)ART

- In STM32L4 and STM32L4+ devices, the U(S)ARTs clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - HSI16 clock
 - LSE clock
 - APB1 or APB2 clock (PCLK1 or PCLK2 depending on which APB is mapped to the U(S)ART)
- In STM32U575/585 devices, the U(S)ARTs clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - PCLK2
 - LSE
 - HSI16

LPTIM

- In STM32L4 and STM32L4+ devices, the LPTIMx clock is derived from one of the following sources (selected by software):
 - LSI clock
 - LSE clock
 - HSI16 clock
 - APB1 clock (PCLK1)
 - External clock mapped on LPTIMx_IN1
- In STM32U575/585 devices, the LPTIMx clock is derived from one of the following sources (selected by software):
 - APB1 clock (PCLK1)
 - LSI
 - LSE
 - HSI16

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LPUART

- In STM32L4 and STM32L4+ devices, the LPUART1 clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - APB1 clock (PCLK1)
 - LSE
 - HSI16 clock (only for STM32L4+ and STM32L41/42/43/44/45/46xxx)
 - HSI clock (only for STM32L4x1/4x5/4x6xx).
- In STM32U575/585 devices, the LPUART1 clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - MSIK
 - LSE
 - HSI16

SPI

- STM32L4 and STM32L4+ devices do not have a dedicated clock for SPI.
- In STM32U575/585 devices, the SPI clock is derived from one of the following sources (selected by software):
 - system clock (SYSCLK)
 - APBx clock (PCLKx)
 - MSIK
 - HSI16

(S)AES

In STM32U575/585 devices, the (S)AES clock is derived from the SHSI RC oscillator.

Note: (S)AES is not available on STM32L4 and STM32L4+.

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4.3.7 Power controller (PWR)

The STM32U575/585 implement the same PWR features than STM32L4 and STM32L4+, but with some specification updates and enhancements.

In STM32L4, STM32L4+ and STM32U575/585, several peripherals are supplied through independent power domains: VDDA, VDDIO2 and VDDUSB. These supplies must not be provided without a valid operating supply on the VDD pin.

STM32L412/433/452/4x6xx and STM32L4Rx allow an external SMPS (DC-DC) power converter to be connected. Moreover, the STM32U575/585 integrate an SMPS(DC-DC) power-converter function in parallel to the LDO, with on-the-fly selection, for optimum power consumption and noise filtering.

In STM32U575/585, the SMPS power-supply pins are available only on specific packages embedding an SMPS step-down converter. If the selected package features the SMPS step-down converter option but this converter is never used by the application, it is recommended to set the SMPS power-supply pins as follows:

- VDDSMPS and VLXSMPS connected to VSS.
- VDD11 pins connected to VSS through two 2.2 μF capacitors as in normal mode.

Table 20. PWR features of STM32L4, STM32L4+ and STM32U575/585

Features	STM32L4/L4+	STM32U575/585				
Power supplies	 V_{DD} = 1.71 to 3.6V: external power supply for I/Os, Flash memory and internal regulator It is provided externally through VDD pins. 	V _{DD} = 1.71 to 3.6 V: external power supply for I/Os, the internal regulator, and the system analog such as reset, power management and internal clocks It is provided externally through VDD pins.				
	 V_{CORE} = 1.0 to 1.28 V: power supply for digital peripherals, SRAM and Flash memory It is generated by an internal voltage regulator. Two V_{CORE} ranges can be selected by software depending on target frequency. 	 V_{CORE} = 0.9 to 1.2 V: power supply for digital peripherals, SRAM and Flash memory It is generated by an internal voltage regulator. Four V_{CORE} power ranges (1, 2, 3, 4) can be programmed by software depending on target frequency. 				
	V_{BAT} = 1.55 to 3.6 V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when V_{DD} is not present	$\label{eq:VBAT} V_{BAT} = 1.55 \ to \ 3.6 \ V:$ when V_{DD} is not present, V_{BAT} is the power supply for RTC, external clock 32 kHz oscillator, backup registers and optionally backup SRAM .				
	Independent power supplies (V_{DDA} , V_{DDIO2} , V_{DDUSB}) allow a lower supply voltage than analog and USB.	reduction of the power consumption by running MCU at				
	 V_{SSA}, V_{DDA} = 1.62 to 3.6 V (ADCs/COMPs) / 1.8 to 3.6 V (DAC/OPAMPs) / 2.4 V to 3.6 V (VREFBUF) 	 V_{SSA}, V_{DDA} = 1.62 to 3.6 V (ADCs, COMPs, DACs, OPAMPs) / 1.8 to 3.6 V (VREFBUF) 				
	 V_{DDA} is the external analog power supply for ADCs and DACs, voltage reference buffer, operational amplifiers and comparators. 	 V_{DDA} is the external analog power supply for ADCs and DACs, voltage reference buffer, operational amplifiers and comparators. 				
	The VDDA voltage level is independent from the VDD voltage.	• The V_{DDA} voltage level is independent from the V_{DD} voltage.				
	 V_{DDUSB} = 3.0 to 3.6 V: external independent power sup The V_{DDUSB} voltage level is independent from the V_{DD} 	• •				
	 V_{DDIO2} = 1.08 V to 3.6 V: external power supply for 14 I/Os (Port G[15:2]) V_{DDIO2} voltage level is independent from the V_{DD} voltage (not applicable for STM32L41/42/43/44/45/46xxx) 					

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Features	STM32L4/L4+	STM32U575/585				
	N/A	 V_{DDSMPS} = 1.71 V to 3.6 V: external power supply for the SMPS step-down converter. It is provided externally through VDDSMPS supply pin, and must be connected to the same supply as VDD pin. V_{LXSMPS} is the switched SMPS step-down converter output. An external coil with typical value of 2.2 μH to be connected between the dedicated VLXSMPS pin to VSSSMPS, via a capacitor of 4.7 μF. 				
Power supplies	 V_{LCD} = 2.5 to 3.6 V Available only on SM32L4R9/4S9xx: V_{DDDSI} is an independent DSI power supply dedicated for the DSI regulator and the MIPI D-PHY. It must be connected to VDD. Available only on SM32L4R9/4S9xx: V_{CAPDSI} is the output of the DSI regulator (1.2 V), that must be connected externally to VDD12DSI. Available only on SM32L4R9/4S9xx: V_{DD12DSI} is used to supply the MIPI D-PHY, and to supply the clock and data lanes pins. An external capacitor of 2.2 μF must be connected on the VDD12DSI pin. 	N/A				
Battery Backup domain	 RTC with backup registers (128 bytes) LSE PC13 to PC15 I/Os 					
Power supply supervisor	 Integrated POR/PDR circuitry Programmable voltage detector (PVD) Brownout reset (BOR) BOR is always enabled, except in Shutdown mode. Four peripheral voltage monitoring (PVM): PVM1 for V_{DDUSB} (~1.2 V) PVM2 for V_{DDIO2} (~0.9 V) PVM3/PVM4 for V_{DDA} (~1.65 V/ ~2.2 V) 	Four peripheral voltage monitoring (PVM): UVM for V _{DDUSB} (~1.2V) IO2VM for VDDIO2 (~0.9V) AVM1/AVM2 for V _{DDA} (~1.6 V/~1.8V)				
Low-power modes	Sleep mode Low-power run mode (up to 2 MHz) Low-power sleep mode (up to 2 MHz) System clock is limited to 2 MHz. I2C and U(S)ART/LPUART can be clocked with HSI16 at 16 MHz. Consumption is reduced at lower frequency thanks to the low-power regulator. Stop 0 and Stop 1 modes ⁽¹⁾	Range 4 in voltage scaling (24 MHz)				
	 Stop 2 mode for STM32L4 Stop 2 mode for STM32L4+: SRAM3 enabled (RRSTP = 1) and disabled (RRSTP = 0) within PWR_CR1 register 	Stop 2 mode ⁽¹⁾				
	N/A	Stop 3 mode ⁽¹⁾ : Functional peripherals and sources of wakeup reduced to the same ones as in Standby mode.				

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Features	STM32L4/L4+	STM32U575/585			
Low-power modes	 Standby mode (VCORE domain powered off) Optional SRAM2 retention Optional I/O pull-up or pull-down configuration 	 Standby mode (VCORE domain powered off) Full SRAM2 content or 8 Kbytes or 56 Kbytes can be retained Optional I/O pull-up or pull-down configuration 			
	Shutdown mode (VCORE domain powered off and power mo	onitoring off)			
External SMPS	 Support for external SMPS for high-power efficiency Refer to the application note <i>Design</i> recommendations for STM32L4xxxx with external SMPS, for ultra-low-power applications with high performance (AN4978) for STM32L4 Series. 	N/A			
	Sleep mode: any peripheral interrupt/wakeup event				
	Stop 0, Stop 1 and Stop 2 modes: any EXTI line event/interrupt BOR, PVD, PVM, COMP, RTC, USB, IWDG, U(S)ART, LPUART, I2C, SWP, LPTIM, LCD	Stop 0, Stop 1 and Stop 2 modes: any EXTI line event/interrupt			
Wakeup sources	Standby mode: 5 WKUP pins configurable rising or falling edge RTC event external reset in NRST pin IWDG reset	Standby mode:			
	Wakeup from Sleep (Sleep-now or Sleep-on-exit): same as b	pefore entering Sleep mode.			
System clock after wakeup	Wakeup from Stop: HSI16 (16 MHz) or MSI (all ranges up to 48 MHz) allowing 5 μ s wakeup at high speed, without waiting for PLL startup time.	Wakeup from Stop: MSIS up to 24 MHz or HSI16, depending on software configuration.			
	Wakeup from Standby: MSI (from 1 to 8 MHz)	Wakeup from Standby: MSIS (from 1 to 4 MHz)			
	Wakeup from Shutdown: MSI (4 MHz)	Wakeup from Shutdown: MSIS (4 MHz)			

^{1.} For STM32U575/585, some peripherals are autonomous and can operate in Stop mode by requesting their kernel clock and their bus (APB or AHB) when needed.

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The following figures present the power supply for STM32L4, STM32L4+ and STM32U575/585.

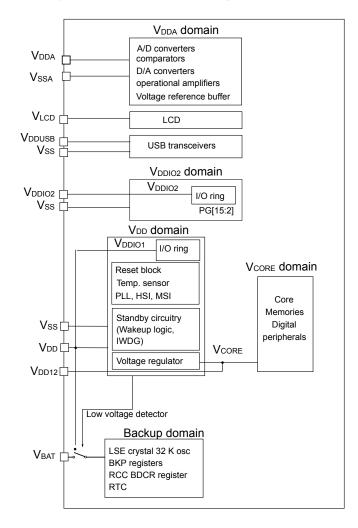


Figure 4. STM32L4 power supply overview

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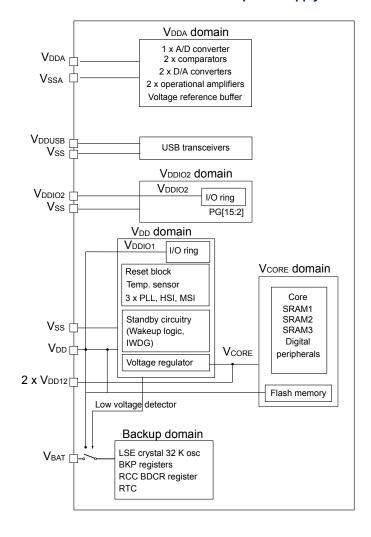


Figure 5. STM32L4P5/4Q5/4S5/4R5/4S7/4R7xx power supply overview

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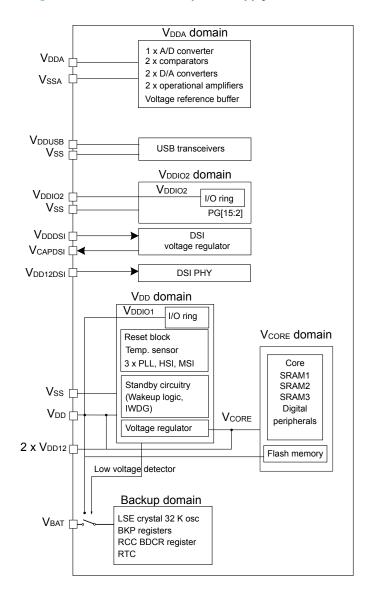


Figure 6. STM32L4R9/4S9xx power supply overview

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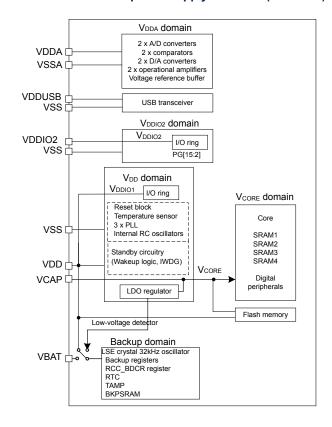
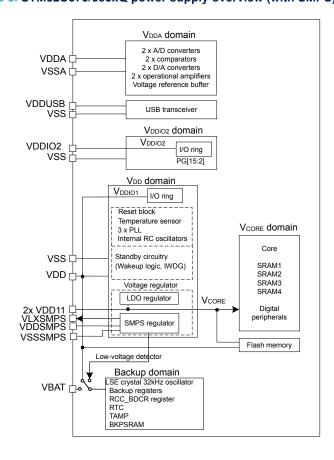


Figure 7. STM32U575/585xx power supply overview (no SMPS)





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4.3.8 General-purpose I/Os (GPIO)

The STM32U575/585 implement the same GPIO features than STM32L4 and STM32L4+, but with additional TrustZone security support.

For STM32U575/585, each GPIO port has four 32-bit configuration registers (GPIOx_MODER, GPIOx_OTYPER, GPIOx_OSPEEDR and GPIOx_PUPDR), two 32-bit data registers (GPIOx_IDR and GPIOx_ODR) and a 32-bit set/reset register (GPIOx_BSRR).

In addition, all GPIOs in STM32U575/585 have a 32-bit locking register (GPIOx_LCKR) and two 32-bit alternate function selection registers (GPIOx_AFRH and GPIOx_AFRL), a secure configuration register (GPIOx SECCFGR) and a high-speed low-voltage register (GPIOx HSLVR).

Each general-purpose I/O pin of GPIO port in STM32U575/585 can be individually configured as secure/non-secure in the GPIOx_SECCFGR register. After reset, all general-purpose I/O of GPIO ports are secure.

All GPIO registers can be read and written by privileged and unprivileged accesses, whatever the security state secure or non-secure.

In addition to the GPIO peripheral, the STM32U575/585 embed a low-power general-purpose input/output (LPGPIO) that is designed to be used in conjunction with the GPIO interface and allows the I/O control in Stop mode (down to Stop 2 mode), using DMA in memory-to-memory transfer mode.

For more information about the STM32U575/585 GPIO and LPGPIO programming and usage, as well as TrustZone security, refer to the "General-purpose I/Os (GPIO)" and "Low-power general-purpose I/Os (LPGPIO)" sections of the reference manual and to the product datasheet for detailed description of the pinout and alternate function mapping.

4.3.9 Extended interrupt and event controller (EXTI)

The STM32U575/585 implement almost the same EXTI features than STM32L4 and STM32L4+ Series, with two exceptions: STM32U575/585 feature TrustZone security support and privileged/unprivileged mode selection and do not feature direct event inputs.

Feature

STM32L4/L4+
STM32U575/585

Up to 41 lines:

12 direct, 26 configurable on STM324R/4Sxxx

15 direct, 26 configurable on STM32L49/4Axxx

14 direct, 26 configurable on STM32L47/48xxx

12 direct, 25 configurable on STM32L41/42/43/44xxx

Table 21. EXTI features of STM32L4, STM32L4+ and STM32U575/585

EXTI security protection

When security is enabled for an input event, the associated input event configuration and control bits can only be modified and read by a secure access. A non-secure write access is discarded and a read returns 0.

EXTI privilege protection

When privilege is enabled for an input event, the associated input event configuration and control bits can only be modified and read by a privileged access. An unprivileged write access is discarded and a read returns 0.

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The table below presents the EXTI line differences between STM32L4, STM32L4+ and STM32L575/585.

Table 22. EXTI lines of STM32L4, STM32L4+ and STM32U575/585

Line	STM32L4	STM32L4+	STM32U575/585	
17	OTG_FS wakeup event (OTG_FS_WKUP)(1)(2)		COMP1 output	
18	RTC alarms		COMP2 output	
19	RTC tamper or timestamp or CS	S_LSE	VDDUSB voltage monitor	
20	RTC wakeup timer		VDDIO2 voltage monitor	
21	COMP1 output		VDDA voltage monitor 1	
22	COMP2 output		VDDA voltage monitor 2	
30	UART5 wakeup ⁽²⁾	N/A		
34	Reserved	SWPMI1 wakeup ⁽²⁾⁽³⁾		
36	PVM2 wakeup	N/A	N/A	
39	Reserved	LCD wakeup ⁽⁴⁾		
40	I2C4 wakeup	I2C4 wakeup ⁽⁵⁾		

- 1. Not available for STM32L431xx.
- 2. This line source cannot wake up from Stop 2 mode.
- 3. Not available on STM32L41/42/45/46xxx.
- 4. Only available on STM32L4x3/4x5/4x6xx.
- 5. Not available on STM32L41/42/43/44xxx.

4.3.10 Cyclic redundancy check calculation unit (CRC)

The CRC architecture is the same in STM32U575/585, STM32L4 and STM32L4+, supporting the same features, with a minor difference in CRC_IDR, that is extended from an 8-bit register in STM32L4 series to a 32-bit register in STM32L4+ and STM32U575/585.

4.4 Security peripherals

4.4.1 Tamper and backup registers (TAMP)

The STM32U575/585 anti-tamper detection circuit is used to protect sensitive data from external attacks. 32 backup registers, each of 32-bit size, are retained in all low-power modes and also in V_{BAT} mode. The table below compares the tamper pins and internal events and lists the main differences between STM32U575/585, STM32L4+ and STM32L4.

Table 23. Tamper pins and events of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585
Tamper pins (not compatible)	3 tamper pins: PC13(RTC_TAMP1) PA0(RTC_TAMP2) PE6(RTC_TAMP3)	8 inputs/outputs TAMP pins for 8 external tamper detection events: PC13(TAMP_IN1/TAMP_OUT2) PA0 (TAMP_IN2/TAMP_OUT1) PE6(TAMP_IN3/TAMP_OUT6) PC5 (TAMP_IN4/TAMP_OUT5) PA1 (TAMP_IN5/TAMP_OUT4) PE3 (TAMP_IN6/TAMP_OUT3) PE4 (TAMP_IN7/TAMP_OUT8) PE5 (TAMP_IN8/TAMP_OUT7)

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Feature	STM32L4/L4+	STM32U575/585	
TAMP internal events to protect against transient or environmental perturbation attacks	N/A	 11 internal tamper events tamp_itamp1: supply voltage monitoring tamp_itamp2: temperature monitoring tamp_itamp3: LSE monitoring tamp_itamp5: RTC calendar overflow tamp_itamp6: JTAG/SWD access when RDP > 0 tamp_itamp7: voltage monitoring through ADC analog watchdog 1 tamp_itamp8: monotonic counter overflow tamp_itamp9: cryptographic peripheral fault (SAES, AES, PKA or RNG) tamp_itamp11: IDWG reset when tamper flag is set tamp_itamp12: voltage monitoring through ADC analog watchdog 2 tamp_itamp13: voltage monitoring through ADC analog watchdog 3 	
TAMP pins functionality over V _{DD} mode	All tamper pins are functional in all low-power modes when the external V_{DD} power supply is present.		
TAMP pins functionality over V _{BAT} mode	All tampers are functional in V _{BAT} mode.		
Active tamper detection mode		X	
Potential tamper detection mode	N/A	X	
Boot hardware key		Stored in the first backup registersProgrammed during boot for secure AES	
Tamper protected assets	Backup registers	 Backup registers SRAM2 ICACHE/DCACHE content OTFDEC keys and CRC registers SAES, AES, HASH peripherals PKA SRAM RHUK in system Flash memory 	

4.4.2 Hash processor (HASH)

The STM32U575/585, STM32L4+ and STM32L49/4Axxx devices embed a HASH hardware accelerator with same features.

Both hash processors provide an interface to connect to the DMA controller. The STM32U575/585 HASH peripheral supports both single- and fixed-DMA burst transfers of four words. However, the HASH in STM32L4+ and STM32L49/4Axxx devices only support single-DMA transfers.

HASH registers are compatible, except a minor difference on HASH_CR:

- ALGO[0] in bit 7 for STM32L4+ and STM32L49/4Axxx devices
- ALGO[0] in bit 17 for STM32U575/58

4.4.3 On-the-fly decryption engine (OTFDEC)

The OTFDEC decrypts in real-time the encrypted content stored in the external OCTOSPI memories used in Memory-mapped mode. The OTFDEC uses the AES-128 algorithm in counter mode (CTR).

The STM32U575/585 embed two OTFDEC peripherals. While in STM32L4 and STM32L4+, this peripheral is not supported.

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4.4.4 True random number generator (RNG)

The STM32U575/585, STM32L4 and STM32L4R/4Sxxx embed an RNG that delivers 32-bit random numbers generated by an integrated analog circuit, with the same features except the minor differences detailed in the table below.

Table 24. RNG features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4	STM32L4R/4Sxxx (in STM32L4+ Series)	STM32U575/585
True random number generator			
Can be used as entropy source to construct a non- deterministic random bit generator (NDRBG)	X		
Tested using German BSI statistical tests of AIS-31 (T0 to T8)			
Embeds start-up and NIST SP800-90B approved continuous health tests	N/A	>	<
Can be disabled to reduce power consumption	X		
Can be enabled with an automatic low-power mode (default configuration).	N/A X		<
AHB slave peripheral, accessible through 32-bit word single accesses only	X		
RNG internal tamper event signal to TAMP	N/A	,	v
Transparent use by SAES and PKA for DPA resistance	IN/A	/	X

In STM32U575/585, the RNG is transparently used by SAES and PKA for DPA resistance. When an unexpected error is found by the RNG, an internal tamper event is triggered in TAMP peripheral, and the RNG stops delivering random data.

When this event occurs, a secure application needs to reset the RNG, either using the central reset management, or the global SoC reset. Then a proper initialization of the RNG is required, again.

4.4.5 Public key accelerator (PKA)

The STM32U575/585 and STM32L4P5/Q5xx devices embed one PKA peripheral intended for the computation of cryptographic public key primitives within the Montgomery domain. All needed computations are performed within the accelerator, so no further hardware/software elaboration is needed to process the inputs or the outputs.

The STM32U575/585 and STM32L4P5/Q5xx share almost the same PKA features but the STM32U575/585 embed two new features and three new computation operators. Registers are compatible except new bits added in STM32U575/585 to map the new features.

The STM32L4 devices do not support a PKA peripheral.

Table 25. PKA features of STM32L4+ and STM32U575/585

Feature	STM32L4P5/Q5xx (in STM32L4+ Series)	STM32U575/585
RSA modular exponentiation, RSA Chinese remainder theorem (CRT) exponentiation	>	(
ECC scalar multiplication, point on curve check		
ECC complete addition		
ECC double-base ladder	N/A	X
ECC projective to affine		
ECDSA signature generation and verification	X	

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Feature	STM32L4P5/Q5xx (in STM32L4+ Series)	STM32U575/585	
Size of RSA/DH operands (in bits)	3136	4160	
Size of ECC operands (in bits)	640		
Arithmetic and modular operations (such as addition, subtraction, multiplication, modular reduction, modular inversion, comparison and Montgomery multiplication)	X		
Built-in Montgomery domain inward and outward transformations			
Protection against differential power analysis (DPA) and related side- channel attacks	N/A	Х	

4.4.6 AES and SAES hardware accelerators

The STM32U575/585 embed two AES accelerators: one secure AES (SAES) and a faster AES. This is a new feature in STM32U575/585, that is not available in STM32L4 and STM32L4+.

In STM32U575/585, the SAES with hardware unique key embeds protection against differential power analysis (DPA) and related side channel attacks. When an unexpected hardware fault occurs, an output tamper event is triggered, and the AES automatically clears key registers. A reset is required for the AES to be usable again.

The AES can use the SAES as security coprocessor. In this case, the secure application prepares the key in robust SAES, then, when ready, the AES can load this key through a dedicated hardware key bus. Recommended sequences are described in sections 'AES shared key usage' and 'SAES operations with shared keys' of the product reference manual.

4.4.7 Global TrustZone controller (GTZC)

The security architecture of STM32U575/585 is based on Arm TrustZone with the Armv8-M mainline extension. Each GPIO or peripheral, DMA channel, clock configuration register, DCACHE/ICACHE, or small part of Flash memory or SRAM can be configured as trusted or untrusted.

The GTZC embedded in the STM32U575/585 is used to configure secure-TrustZone and privileged attributes within the full system. All details about GTZC are described in the product reference manual.

This controller is a new feature of STM32L575/585 and is not embedded in STM32L4 or STM32L4+.

4.5 Communication peripherals

4.5.1 Serial peripheral interface (SPI)

This section highlights the SPI features implemented on STM32L4, STM32L4+ and STM32U575/585 devices.

Table 26. SPI features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585
SPI peripherals	SPI1, SPI2 and SPI3 (same features in the three instances)	SPI1, SPI2 (full feature set instances) SPI3 (limited feature set instance)
Full-duplex synchronous transfer on three lines	X	X
Half-duplex synchronous transfer on two lines (with bidirectional data line)	×	X
Simplex synchronous transfer on two lines (with unidirectional data line)	×	X
Data size	4- to 16-bit data size selection	4- to 32-bit data size selection on SPI1, SPI2
	N/A	Fixed to 8- and 16-bit only on SPI3
Multimaster or multislave mode capability	X	X

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Baudrate prescalers Protection of configuration and settings Slave select (SS) management Adjustable minimum delays between data and between SS and data flow Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode automatic CRC error checking for Rx mode	One input: PCLK is the unique SPI clock source. Master/slave mode baudrate prescalers up to fPCLK / 2 N/A N/A NSS management by hardware or software for both master and slave: dynamic change of master/slave operations N/A (fixed) N/A X X X X	Two independent clock inputs: peripheral kernel clock (spi_ker_ck) is independent of PCLK. Baudrate prescaler up to kernel frequency / 2 spi_ker_ck prescaler can be bypassed from RCC in master mode. X Hardware or software management of SS for both master and slave X Configurable SS signal polarity and timing, MISO x MOSI swap capability X Programmable number of data within a transaction to control SS and CRC X
Protection of configuration and settings Slave select (SS) management Adjustable minimum delays between data and between SS and data flow Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	baudrate prescalers up to f _{PCLK} / 2 N/A N/A NSS management by hardware or software for both master and slave: dynamic change of master/slave operations N/A (fixed) N/A X X N/A X N/A	frequency / 2 spi_ker_ck prescaler can be bypassed from RCC in master mode. X Hardware or software management of SS for both master and slave X Configurable SS signal polarity and timing, MISO x MOSI swap capability X Y Programmable number of data within a transaction to control SS and CRC X
Adjustable minimum delays between data and between SS and data flow Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	N/A NSS management by hardware or software for both master and slave: dynamic change of master/slave operations N/A (fixed) N/A X X N/A X N/A	from RCC in master mode. X Hardware or software management of SS for both master and slave X Configurable SS signal polarity and timing, MISO x MOSI swap capability X X Programmable number of data within a transaction to control SS and CRC X
Adjustable minimum delays between data and between SS and data flow Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	NSS management by hardware or software for both master and slave: dynamic change of master/slave operations N/A (fixed) N/A X X N/A X X N/A	Hardware or software management of SS for both master and slave X Configurable SS signal polarity and timing, MISO x MOSI swap capability X X Programmable number of data within a transaction to control SS and CRC X
Adjustable minimum delays between data and between SS and data flow Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	hardware or software for both master and slave: dynamic change of master/slave operations N/A (fixed) N/A X X N/A X X X	SS for both master and slave X Configurable SS signal polarity and timing, MISO x MOSI swap capability X X Programmable number of data within a transaction to control SS and CRC X
Configurable SS signal polarity and timing Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	N/A X X N/A	Configurable SS signal polarity and timing, MISO x MOSI swap capability X X Programmable number of data within a transaction to control SS and CRC X
Programmable clock polarity and phase Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	X X N/A X	timing, MISO x MOSI swap capability X X Programmable number of data within a transaction to control SS and CRC X
Programmable data order with MSB-first or LSB-first shifting Programmable transaction data Dedicated transmission and reception flags with interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	X N/A X	X Programmable number of data within a transaction to control SS and CRC X
Programmable transaction data Dedicated transmission and reception flags with Interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	N/A X	Programmable number of data within a transaction to control SS and CRC
Dedicated transmission and reception flags with Interrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	X	transaction to control SS and CRC
nterrupt capability SPI Motorola and Texas Instrument formats support Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode		
Hardware CRC feature can secure communication at the end of transaction by: adding CRC value in Tx mode	X	X
the end of transaction by: adding CRC value in Tx mode		
	CRC fixed to 8- or 16-bit for all SPIs	 SPI1 and SPI2: CRC polynomial length configurable from 9 to 17 bits SPI3: CRC polynomial length configurable from 9 to 17 bits
nterrupt events and error detection with interrupt capability	Interrupts: Transmit TXFIFO ready to be loaded Data received in receive RXFIFO Master mode fault Overrun error TI frame format error CRC protocol error	Interrupts: TxFIFO ready to be loaded Data received in RxFIFO Both TXP and RXP active Transmission Transfer Filled Overrun error Underrun error TI frame format Error CRC error Mode fault End of transfer Master mode suspended TxFIFO transmission complete All the interrupt events can wak eup
FIFO size	N/A Two 32-bit embedded Rx	the system from Sleep mode at each instance Two 16x or 8x 8-bit embedded Rx and

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Feature	STM32L4/L4+	STM32U575/585
Number of transferred data	Number defined by the counter for the SPI transmission DMA channel	Programmable number of data in transaction: SPI1 and SPI2: unlimited, expandable SPI3: up to 1024 (no data counter)
FIFO thresholds	Fixed threshold to 1/2 FIFO or 1/4 FIFO level	Configurable FIFO thresholds (data packing)
Configurable behavior at slave underrun condition	N/A	X (support of cascaded circular buffers)
Autonomous functionality in Stop modes (handling of the transaction flow and required clock distribution) with wakeup from Stop capability	N/A	 SPI 1/2: Stop 0 and Stop 1 modes with wakeup SPI3: Stop 0, Stop 1 and Stop 2 modes
RDY status pin	N/A	Optional status pin RDY signalizing the slave device ready to handle the data flow

SPI autonomous mode

The three SPI peripherals in STM32U575/585 support autonomous operation down to Stop mode, with the following main feature: The SPI can handle and initialize transactions autonomously, requiring no specific system execution interaction till the ongoing transaction ends.

4.5.2 Inter-integrated circuit (I2C)

The I2C peripherals share the same features in STM32U575/585, STM32L4+ and STM32L4. Differences are shown in the table below.

In addition, the STM32U575/585 embed the autonomous mode of I2C peripherals, allowing the I2C to be functional in Stop mode. The autonomous mode can also be used in Run, Sleep or Stop mode.

Table 27. I2C features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585	
Instances	I2C1, I2C2, I2C3 and I2C4		
7- and 10-bit addressing mode			
Standard-mode (up to 100 Kbit/s)			
Fast-mode (up to 400 Kbit/s)	Same feature on all the instances		
Fast-mode Plus with 20 mA output drive I/Os (up to 1 Mbit/s)			
Independent clock			
SMBus/PMBus			
Wakeup from Stop 0 and Stop 1 modes			
Wakeup from Stop 2 mode	Same feature on I2C3		
Autonomous mode	N/A	 I2C1, I2C2 and I2C4 in CD (CPU domain) I2C3 in SRD (SmartRun domain) 	

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4.5.3 Universal synchronous/asynchronous receiver transmitter (USART)

The STM32U575/585 implement the same U(S)ART features than STM32L4 and STM32L4+ but with some specification updates and enhancements. The main differences are stated in the table below.

Table 28. U(S)ART features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4 and STM32L4+	STM32U575/585
Instances	 3 USARTs 2 UARTs for STM32L4+ and STM32L47/48/49/4Axxx 1 UART for STM32L45/46xxx 1 LPUART 	3 USARTs2 UARTs1 LPUART
Baud rate	Up to 10 Mbit/s (when the clock frequency is 80 MHz and oversampling is by 8)	Depends on the frequency (oversampling by 16 or by 8) ⁽¹⁾
Clock	Dual-clock domain allowing: UART functionality and wakeup from Stop mode Convenient baud rate programming independent from the PCLK reprogramming	Dual-clock domain and wakeup from low-power mode
Data	 Word length: programmable (7, 8 or 9 bits) Programmable data order with MSB-first or LSB-first sh 	hifting
Interrupt	14 interrupt sources with flags for STM32L423 interrupt sources with flags for STM32L4+	23 interrupt sources with flags
Autonomous mode	N/A	Autonomous functionality in Stop mode with wakeup from Stop capability.
	 RS232 hardware flow control (CTS/RTS) Continuous communication using DMA Multiprocessor communication Single-wire half-duplex communication IrDA SIR ENDEC block LIN mode SPI master 	 RS232 hardware flow control and RS485 Continuous communication using USART and DMA Multiprocessor communication Single-wire half-duplex communication IrDA SIR ENDEC block LIN mode
Other features	 Wakeup from Stop mode (start bit, received byte, address match) Support for ModBus communication: timeout feature CR/LF character recognition Two internal FIFOs to transmit and receive data (for STM32L4+) SPI slave (for STM32L4+) Receiver timeout interrupt (except LPUART) Auto baud rate detection (except LPUART) Driver enable Swappable TX/RX pin configuration Note: LPUART does not support Synchronous mode (SPI master), Smartcard mode, IrDA, LIN, ModBus, receiver timeout interrupt and auto baud rate detection. Smartcard mode (T = 0, T = 1) are supported. Features are added to support T = 1 (such as receiver inversion) Number of stop bits: 1, 1.5, 2 	 Wakeup from Stop mode (start bit, received byte, address match) ModBus communication: timeout feature CR/LF character recognition Two internal FIFOs to transmit and receive data SPI slave Receiver timeout interrupt (except LPUART) Auto baud rate detection (except LPUART) Driver enable Swappable TX/RX pin configuration Note: LPUART does not support Synchronous mode (SPI master), Smartcard mode, IrDA, LIN, ModBus, receiver timeout interrupt and auto baud rate detection. timeout, block length, end of block detection and binary data

^{1.} Refer to the USART section in the reference manual.

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4.5.4 Serial audio interface (SAI)

The SAI offers a wide set of audio protocols due to its flexibility and wide range of configurations. Many stereo or mono audio applications may be targeted (such as I²S standards, LSB- or MSB-justified, PCM/DSP, TDM, and AC'97 protocols). The SPDIF output is offered when the audio block is configured as a transmitter.

Table 29. SAI features of STM32L4; STM32L4+ and STM32U575/585

Feature	STM32L4	STM32L4+	STM32U575/585
Instances	SAI1 and SAI2 ⁽¹⁾		
I2S, LSB or MSB-justified, PCM/DSP, TDM, AC'97			
Mute mode	Same feature on all available instances		
Stereo/Mono audio frame capability			inetancos
16 slots with configurable size			
Configurable data size: 8-, 10-, 16-, 20-, 24-, 32-bit			
SPDIF			
FIFO size	8 words		
PDM	N/A Available on SAI1 only		n SAI1 only

^{1.} No SAI in STM32L41/42xxx devices. Only SAI1 on STM32L43/44/45/46xxx devices.

4.5.5 Controller area network (CAN)

The main differences related to CAN between STM32L4, STM32L4+ and STM32U575/585 are presented in the table below.

Table 30. CAN features of STM32L4, STM32L4+ and STM32U575/585

CAN	STM32L4 and STM32L4+	STM32U575/585
Instances	 x1 on STM32L4+ and STM32L43/44/45/46/47/48xxx x2 on STM32L49/4Axxx Not available on STM32L41/42xxx 	x1 FDCAN
Features	 Supports CAN protocol version 2.0 A, B active Bit rates up to 1 Mbit/s Supports the time triggered communication option Tx: 3 transmit mailboxes, configurable priority, time stamp on SOF transmission Rx: 2 receive FIFOs with 3 stages, scalable filter banks, identifier list, configurable FIFO overrun, time stamp on SOF reception Time-triggered communication option: Disable automatic retransmission mode 16-bit free running timer Time Stamp sent in last two data bytes Management Maskable interrupts Software-efficient mailbox mapping at a unique address space 	 Conform with CAN protocol version 2.0 part A, B and ISO 11898-1: 2015, -4 CAN FD with maximum 64 data bytes supported CAN error logging AUTOSAR and J1939 support Improved acceptance filtering Rx: 2 receive FIFOs of 3 payloads each (up to 64 bytes per payload) Separate signaling on reception of high-priority messages Configurable transmit FIFO/queue of 3 payloads (up to 64 bytes per payload) Transmit event FIFO Programmable loop-back test mode Maskable module interrupts 2 clock domains: APB bus interface and CAN core kernel clock Power down support Dual-interrupt lines

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4.5.6 Secure digital input/output MultiMediaCard interface (SDMMC)

The STM32U575/585 embed two SDMMC instances, and implement the same SDMMC features than STM32L4 and STM32L4+, but with some specification updates.

Note: SDMMC is not available on STM32L41/42xxx and STM32L432/442xx.

Table 31. SDMMC features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4	STM32L4+	STM32U575/585
Bus		APB2	
Clock source	MSI clockPLL/QPLLSAI1/Q	MSI clock PLL/Q PLLSAI1/Q HSI48 ⁽¹⁾	 Main PLL VCO (PLL48M1CLK) PLLSAI1 VCO (PLL48M2CLK) MSI clock HSI48
	Full compliance with MultiMediaCard system specification version 4.2. Card support for three different databus modes: 1-bit (default), 4-bit and 8-bit	Full compliance with MultiMediaCard system specification version 4.51. Card support for three different databus modes: 1-bit (default), 4-bit and 8-bit	Full Compliance with embedded MultiMediaCard system specification version 5.1. Card support for three different databus modes: 1-bit (default), 4-bit and 8-bit. HS200 SDMMC_CK speed limited to maximum allowed I/O speed. HS400 not supported
	Full compliance with SD memory card specification version 2.0	Full compliance with SD memory card specification version 4.1	Full compliance with SD memory card specification version 6.0
Other features	Full compliance with SD I/O card specification version 2.0	Full compliance with SDIO card specification version 4.0.	Full compliance with SDIO card specification version 4.0.
	Card support for two different databus modes: 1-bit (default) and 4-bit	Card support for two different databus modes: 1-bit (default) and 4-bit	Card support for two different databus modes: 1-bit (default) and 4-bit
	Data transfer up to 50 MHz for the 8-bit mode	Data transfer up to 104 Mbyte/s for the 8-bit mode	Data transfer up to 208 Mbyte/s for the 8-bit mode
		DMA is used to provide high-speed transfer between the SDMMC FIFO and the memory.	
	N/A	The SDMMC internal DMA (IDMA) provides one channel to be used either for transmit or receive.	
		N/A	IDMA linked list support

^{1.} Only on STM32L4+ and STM32L43/44/45/46/49/4Axxx.

4.5.7 Digital camera interface (DCMI) and parallel synchronous slave interface (PSSI)

The DCMI is available on STM32L49/4Axx, STM32L4+ and STM32U575/585 devices. The PSSI is only available on STM32L4P5/Q5xx and STM32U575/585 devices.

DCMI and PSSI use the same circuitry and then, when they are both implemented on a device, they cannot be used at the same time: when using the PSSI, DCMI registers cannot be accessed, and vice-versa. In addition, PSSI and DCMI share the same alternate functions and interrupt vector.

The DCMI main features are the following:

- 8-, 10-, 12- or 14-bit parallel interface
- Embedded/external line and frame synchronization
- Continuous or snapshot mode
- Crop feature

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- Data formats supported:
 - 8-, 10-, 12-, and 14-bit progressive video (either monochrome or raw Bayer)
 - YCbCr 4:2:2 progressive video
 - RGB 565 progressive video
 - Compressed data JPEG

The PSSI peripheral main features are listed below:

- Slave mode operation
- 8- or 16-bit parallel data input or output
- 8-word (32-byte)
- Data enable (PSSI_DE) alternate function input and ready (PSSI_RDY) alternate function output

4.5.8 Universal serial-bus interface (USB)

The STM32L4, STM32L4+ and STM32U575/585 have different USB peripherals:

- USB OTG FS implemented in STM32U575/585, STM32L4+ and STM32L47/48/49/4Axx
- USB FS implemented in STM32L41/42/43/44/45/46xxx

On STM32U575/585, STM32L4+ and STM32L41/42/43/44/45/46/49/4Axx, an included CRS (clock recovery system) provides a precise clock to the USB peripheral:

- When using USB device mode, the CRS allows crystal-less USB operation.
- When using USB host mode, the CRS allows low frequency crystal (32.768 kHz) USB operation.

Most OTG_FS features supported by STM32L4 and STM32L4+ are also supported by STM32U575/585.

Table 32. USB features of STM32L4, STM32L4+ and STM32U575/585

Features	STM32L4/L4+	STM32U575/585	
	 Full support for the USB OTG_FS without clock recovery (for STM32L476/486xx) Full support for the USB OTG_FS) with clock recovery (only on STM32L4+ and STM32L47/48/49/4Axxx) USB FS device (only on STM32L41/42/43/44/45/46xxx) 	Full support for the USB OTG_FS with clock recovery.	
General	FS mode: • For STM32L4+ and STM32L47/48/49/4Axxx: - 1 bidirectional control endpoint - 5 IN endpoints (bulk, interrupt, isochronous) 12 configurable endpoints: • 1 bidirectional control endpoint		
	 Attach detection protocol (ADP) (only on STM32L4+ and STM32L47/48/49/4Axxx) Battery charging detection (BCD) 	Attach detection protocol (ADP)Battery charging detection (BCD)	
	Independent V _{DDUSB} power supply allowing lower V _{DDCORE} while using USB		
	USB internal connect/disconnect feature with an internal pull-up resistor on the USB D+ (USB_DP) line	N/A	
Mapping	 APB1 for STM32L4+ and STM32L47/48/49/4Axxx AHB2 for STM32L14/42/43/44/45/46xxx 	AHB2	

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Features	STM32L4/L4+	STM32U575/585
Buffer memory	 1.25-Kbyte data FIFOs management of up to 6 Tx FIFOs (1 for each IN end point) + 1 Rx FIFO (for STM32L4+ and STM32L47/48/49/4Axxx) 1024 bytes of dedicated packet buffer memory SRAM (for STM32L41/42/43/44/45/46xxx) 	1.25-Kbyte data FIFOs management of up to 6 Tx FIFOs (1 for each IN end point) + 1 Rx FIFO
Low-power modes	 USB suspend and resume USB revision 2.0 including link power management (LPM) support 	 System stop during USB suspend Switch-off of clock domains internal to the digital core PHY and DFIFO power management USB revision 2.0 including link power management (LPM) support

4.6 Analog peripherals

4.6.1 Analog-to-digital converter (ADC)

The STM32U575/585, STM32L4 and STM32L4+ embed:

- two ADCs: ADC1 (14-bit resolution) and ADC4 (12-bit resolution) for STM32U575/585, both up to 2.5 Msps
- two ADCs: ADC1 and ADC2 for STM32L41/42/43/44/45/46xxx and STM32L4+, both consist of a 12-bit successive approximation ADC that are tightly coupled and can operate in dual mode (ADC1 is master).
- three ADCs: ADC1, ADC2 and ADC3 (12-bit resolution) for STM32L4x1/47x/48x/49x/4Axxx:
 - ADC1 and ADC2 are tightly coupled and can operate in dual mode (ADC1 is master).
 - ADC3 is controlled independently.
- ADC4 only on STM32U575/585: It does not support differential inputs and injected channels, but it supports
 the autonomous mode.

Table 33. ADC features of STM32L4, STM32L4+ and STM32U575/585

	Feature	SIM32LAV1/A/V/AXV/AQV/AAVVV		STM32L41/42/43/44/45/46xx x and STM32L4+	STM32l	J575/585
		ADC1, ADC2	ADC3	ADC1, ADC2	ADC1	ADC4
Resolu	ition		12 bits		14 bits	12 bits
Configures olut			12, 10, 8 or 6 bits		14, 12, 10, or 8 bits	12, 10, 8 or 6 bits
Single-	ended inputs			X		
Differe	ntial inputs					
Injecte	d channel sion	X N/A			N/A	
Dual m	node	Up to two ADCs can operate in dual mode: ADC1 connected to 16 external channels and 3 internal channels ADC2 connected to 16 external channels + 2 internal channels.	ADC3 connected to 12 external channels and 4 internal channels	Up to two ADCs can operate in dual mode ⁽¹⁾ : ADC1 connected to 16 external channels and 3 internal channels ADC2 connected to 16 external channels + 2 internal channels.	N	/A
	Ratio	Up to 256x		Up to 1024	Up to 256x	
Overs ampli	Data register	16 bits 32		32 bits	16 bits	
ng	Programmabl e data shift			Right and left shift	Up to 8 bits shift	
DMA s	upport	X				

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Feature	STM32L4x1/47x/48x	c/49x/4Axxx	STM32L41/42/43/44/45/46xx x and STM32L4+ STM32U5		J575/585
	ADC1, ADC2	ADC3	ADC1, ADC2	ADC1	ADC4
Autonomous mode	N/A X			X	
Number of analog watchdogs	3				

^{1.} Only available on STM32L4P5/Q5xx for STM32L4+ devices.

4.6.2 Digital-to-analog converter (DAC)

DAC peripherals in STM32L4, STM32L4+ and STM32U575/585 have identical electrical parameters and configuration options, with two differences in the new autonomous mode and double-data DMA capability for STM32U575/585:

- Autonomous mode to reduce the power consumption for the system
 The autonomous mode can be used to update the DAC output voltage in Stop mode. This allows DMA transfers to be performed when the device operates in Run, Sleep or Stop mode. The autonomous mode is supported only when the DAC is in sample-and-hold mode.
- Double-data DMA capability to reduce the bus activity
 When the DMA controller is used in normal mode, only 12-bit (or 8-bit) data are transferred by a DMA request. As the AHB width is 32 bits, two 12-bit data may be transferred simultaneously.

Feature	STM32L4 ⁽¹⁾	STM32L4+	STM32U575/585	
Number of instances	1 ⁽²⁾	1	1	
Resolution		12 bits		
Dual channel	X ⁽³⁾			
Output buffer	X			
I/O connection	DAC1_OUT1 on PA4 and DAC1_OUT2 on PA5 ⁽³⁾			
Maximum sampling time	1 Msps			
Autonomous mode	N/A X		X	
Double-data DMA	- IN	/A	^	

Table 34. DAC features of STM32L4, STM32L4+ and STM32U575/585

- 1. No DAC in the STM32L41/42xxx devices.
- 2. Two instances in STM32L4x1xx devices (one output channel each).
- 3. Only single channel on STM32L451/452/462xx devices (DAC1_OUT1 on PA4 as I/O connection).

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4.6.3 Comparator (COMP)

Each STM32L4, STM32L4+ and STM32U575/585 embeds two ultra-low-power comparators, COMP1 and COMP2, with identical electrical parameters.

Comparators for STM32L4 and STM32L4+ have the same configuration options that are different from STM32U575/585 ones: COMP1_CSR and COMP2_CSR registers are not compatible. Differences are listed in the table below.

Table 35. COMPx_CSR registers of STM32L4, STM32L4+ and STM32U575/585

COMPx_CSR bit	STM32L4/L4+	STM32U575/585	
Bit 0	EN: COMPx ⁽¹⁾ enable		
Bits 3:2	PWRMODE[1:0]: Power mode of the comparator x		
Bits 6:4	INMSEL: Comparator x input minus selection bits	INMSEL[3:0]: COMPx signal selector for inverting input	
Bit 7	INPSEL: Comparator x input plus selection bit	INM	
Bits 9:8	Reserved: for COMP1_CSR Bit 9: WINMODE: Windows mode selection bit for COMP2_CSR (Bit 8: reserved)	INPSEL[1:0]: COMPx signal selector for non-inverting input	
Bit 11	Reserved	WINMODE: COMPx non-inverting input selector for Window mode	
Bit 14	Reserved	WINOUT: COMPx output selector	
Bit 15	POLARITY: COMPx polarity selector		
Bits 17:16	HYST[1:0]: COMPx hysteresis selector		
Bits 19:18	BLANKING[2:0]: Comparator x blanking source	PWRMODE[1:0]: COMPx power mode selector	
Bit 20	selection bits		
Bit 21	Reserved		
Bit 22	BRGEN: Scaler bridge enable	Bits 24:20 BLANKSEL[4:0]: COMPx blanking source selector	
Bit 23	SCALEN: voltage scaler enable bit		
Bit 24	Reserved		
Bit 30	VALUE: COMPx output status		
Bit 31	LOCK: COMPx_CSR register lock		

^{1.} x corresponds to the number of COMP instance used (1 or 2).

There is also one difference in the new blanking sources for STM32U575/585:

- TIM3 OC3 is added as blanking source in COMP1.
- TIM3 OC4, TIM8 OC5 and TIM15 OC1 are added as blanking sources in COMP2.

4.6.4 Voltage reference buffer (VREFBUF)

The internal VREFBUF is an operational amplifier, with programmable gain. The amplifier input is connected to the internal voltage reference VREFINT. STM32U575/585, STM32L4 and STM32L4+ devices embed one VREFBUF that can be used as voltage reference for ADCs and DACs. VREFBUF can also be used as voltage reference for external components through the VREF+ pin.

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The STM32U575/585 VREFBUF supports four voltages, when the STM32L4 and STM32L4+ support only two voltages.

Table 36. VREFBUF features of STM32L4, STM32L4+ and STM32U575/585

STM32L4/L4+ ⁽¹⁾		STM32U575/585	
Symbol Voltage (V)		Symbol	Voltage (V)
NIA		VREFUBUF0	1.5
IN	N/A		1.8
VREF_OUT1	VREF_OUT1 2.048		2.048
VREF_OUT2 2.5		VREFUBUF3	2.5

^{1.} No VREFBUF in STM32L41/42xxx devices.

4.6.5 Operational amplifier (OPAMP)

The two OPAMP1 and OPAM2 (two inputs and one output each) in STM32U575/585, STM32L4 and STM32L4+ devices have identical features. The three I/Os can be connected to the external pins to enable any type of external interconnections.

Each OPAMP can be configured internally as a follower or as an amplifier with a non-inverting gain ranging from 2 to 16. The positive input can be connected to the internal DAC. The output can be connected to the internal ADC.

The only difference is that the STM32U575/585 OPAMPs support the high-speed mode and achieves a better slew rate.

4.7 Timer peripherals

The STM32U575/585, STM32L4+ and STM32L4 devices include two advanced-control timers, up to seven general-purpose timers, two basic timers, up to four low-power timers (two for STM32L4 and STM32L4+), two watchdog timers and two SysTick timers.

This section compares the features of the above listed timers and RTC in STM32L4, STM32L4+ and STM32U575/585 devices.

4.7.1 Advanced-control timers (TIM1/8)

The STM32U575/585, STM32L4+ and STM32L4 include two advanced-control timers, TIM1 and TIM8, with identical features detailed in the table below (only TIM1 for STM32L41/42/43/44/45/46xxx devices).

Table 37. Advanced-control timer (TIM1/8) features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4, STM32L4+ and STM32U575/585	
Counter resolution and type	16-bit up, down, up/down auto-reload counter	
Prescaler factor	16-bit programmable prescaler used to divide (also on-the-fly) the counter clock frequency by any factor between 1 and 65536	
Channels	 Up to six independent channels for: Input capture (but channels 5 and 6) Output compare PWM generation (edge and center-aligned mode) One-pulse mode output 	
Complementary outputs	Complementary outputs with programmable dead-time	
Synchronization with external signals and general-purpose timers	Synchronization circuit to control the timer with external signals and to interconnect several timers together. The advanced-control (TIM1/TIM8) and general-purpose (TIMx) timers are completely independent, and do not share any resources.	
Repetition counter	Repetition counter to update the timer registers only after a given number of counter cycles	

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Feature	STM32L4, STM32L4+ and STM32U575/585
Break inputs	Two break inputs to put the timer output signals in a safe user selectable configuration
Interrupt/DMA generation	Interrupt/DMA generation on the following events: Update: counter overflow/underflow, counter initialization (by software or internal/external trigger) Trigger event (counter start, stop, initialization or count by internal/external trigger) Input capture Output compare
Encoders and sensors	Support incremental (quadrature) encoder and Hall-sensor circuitry for positioning purposes
Trigger input	Trigger input for external clock or cycle-by-cycle current management
Application examples	 Measuring the pulse lengths of input signals (input capture) Generating output waveforms (output compare, PWM, complementary PWM with dead-time insertion)

4.7.2 GP timers with up, down, up-down auto-reload counter (TIM2/3/4/5)

The GP (general-purpose) timers consist of a 16-bit or 32-bit auto-reload counter driven by a programmable prescaler. The STM32U575/585, STM32L4+ and STM32L4 devices include GP timers with up, down or updown auto-reload counter (TIM2, TIM3, TIM4 and TIM5), with identical features (TIM4/5 only available on STM32L4x1/47x/48x/49x/4Axxx, TIM3 only available on STM32L4x1/451/452/462/47x/48x/49x/4Axxx).

Table 38. GP timer (TIM2/3/4/5) features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585	
32-bit resolution	TIM2/TIM5	TIM2/TIM3/TIM4/TIM5	
16-bit resolution	TIM3/TIM4	-	
Counter resolution and type	16- or 32-bit up, down, up/down auto-reloa	ad counter	
Prescaler factor	16-bit programmable prescaler used to div frequency by any factor between 1 and 65	•	
Channels	Up to four independent channels for: Input capture Output compare PWM generation (edge and center-aligned mode) One-pulse mode output		
Synchronization with external circuits and other timers	Synchronization circuit to control the timer with external signals and to interconnect several timers		
Interrupt/DMA generation	Interrupt/DMA generation on the following events: Update: counter overflow/underflow, counter initialization (by software or internal/external trigger) Trigger event (counter start, stop, initialization or count by internal/external trigger) Input capture Output compare		
Encoders and sensors	Supports incremental (quadrature) encoder and Hall-sensor circuitry for positioning purposes		
Trigger input	Trigger input for external clock or cycle-by-cycle current management		
Application examples	 Measuring the pulse lengths of input signals (input capture) Generating output waveforms (output compare, PWM, complementary PWM with dead-time insertion) 		

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4.7.3 GP timers with auto-reload up-counter (TIM15/16/17)

The STM32U575/585, STM32L4+ and STM32L4 devices include three 16-bit resolution GP timers with a 16-bit auto-reload up-counter (TIM15, TIM16 and TIM17) with identical features (no TIM17 on STM32L41/42/43/44/45/46xxx).

Table 39. GP timer (TIM15/16/17) features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4, STM32L4+ and STM32U575/585		
Counter resolution and type	16-bit auto-reload up-counter		
Prescaler factor	16-bit programmable prescaler used to divide (also on-the-fly) the counter clock frequency by any factor between 1 and 65536		
Channels	Up to two independent channels for: Input capture Output compare PWM generation (edge mode) One-pulse mode output		
Complementary outputs	Complementary outputs with programmable dead-time (for channel 1 only)		
Synchronization with external circuits and other timers	Synchronization circuit to control the timer with external signals and to interconnect several timers		
Repetition counter	Repetition counter to update the timer registers only after a given number of counter cycles		
Break inputs	One break input to put the timer output signals in the reset state or a known state		
Interrupt/DMA generation	Interrupt/DMA generation on the following events: Update: counter overflow/underflow, counter initialization (by software or internal/external trigger) Trigger event (counter start, stop, initialization or count by internal/external trigger) Input capture Output compare Break input (interrupt request)		
Application examples	 Measuring the pulse lengths of input signals (input capture) Generating output waveforms (output compare, PWM, complementary PWM with detime insertion) 		

4.7.4 Basic timers (TIM6/7)

The basic timers TIM6 and TIM7 consist in a 16-bit auto-reload counter driven by a programmable prescaler. These timers are completely independent, and do not share any resources.

The STM32U575/585, STM32L4 and STM32L4+ devices have the same basic timers features.

Table 40. Basic timer (TIM6/7) features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4, STM32L4+ and STM32U575/585		
Counter resolution and type	16-bit auto-reload up-counter		
Prescaler factor	16-bit programmable prescaler used to divide (also on-the-fly) the counter clock frequency by any factor between 1 and 65536		
Synchronization signals	Synchronization circuit to trigger the DAC		
Interrupt/DMA generation	Interrupt/DMA generation on the update event, counter overflow		
Application examples	Time-base generationDriving the DAC		

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4.7.5 Low-power timers (LPTIM1/2/3/4)

The LPTIMx is a 16-bit timer that benefits from the ultimate developments in power-consumption reduction. The STM32U575/585 include four LPTIMs versus two in the STM32L4 and STM32L4+. LPTIMs share the same features in these series, but new features are added in STM32U575/585 such as:

- Two independent channels per LPTIM
- · Input capture channel
- DMA requests
- · Autonomous function in Stop modes

Table 41. LP timer (LPTIMx) features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4	STM32L4+	STM32U575/585
LPTIMx	LPTIM1 and LPTIM2 LPTIM1, LPTIM2, LPTIM3 and LPTIM4		
Counter resolution and type	16-bit up-counter		
Prescaler factor	3-bit prescaler with eight po	essible dividing factors (1, 2,	4, 8, 16, 32, 64 or 128)
Selectable clock	 Internal clock sources: LSE, LSI, HSI or APB clock External clock source over LPTIMx input (working with no low-power oscillator running, used by pulse counter application) 		
Auto-reload	16-bit ARR auto-reload regi	ster	
Capture/compare	16 bit compare register		16-bit capture/compare register
Continuous mode	Continuous/one-shot mode		
Trigger mode	Selectable software/hardware input trigger		
Glitch filter	Programmable digital glitch filter		
Configurable output	Configurable output: pulse, PWM		
Polarity	Configurable I/O polarity		
Encoder mode		X	
Repetition counter	X ⁽¹⁾	X ⁽²⁾	X
Input capture, PWM and one-pulse channels	 Input capture PWM generation (edge mode) 		PWM generation (edge aligned mode)
DMA requests	events: • Update		Update event

- 1. Only available on STM32L41/42xxx devices.
- 2. Only available on STM32L4P5/4Q5xx devices.

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Some of the above features are not similarly implemented on LPTIMx instances, as described in the table below.

Table 42. Implementation of LPTIMx features on various instances

Factions	STM32	L4/L4+	STM32U575/		1575/585	5/585	
Feature	LPTIM1	LPTIM2	LPTIM1	LPTIM2	LPTIM3	LPTIM4	
Encoder mode	Х	-	Х	Х	-	-	
PWM mode	-	-	Х	Х	Х	Х	
Input capture	-	-	X	Х	Х	-	
Number of DMA requests	-	-	3	3	3	-	
Autonomous mode	-	-	Х	Х	Х	-	

4.7.6 Watchdogs (WWDG/IWDG)

The STM32U575/585, STM32L4+ and STM32L4 devices embed two watchdogs:

- a system window watchdog (WWDG) with same features
- an independent watchdog (IWDG) with same features, except the STM32U575/585 IWDG capability to generate an early wakeup interrupt

Table 43. IDWG features of STM32L4, STM32L4+ and STM32U575/585

Feature	STM32L4/L4+	STM32U575/585	
LSI used as IWDG kernel clock	×		
Window function			
Early wakeup interrupt generation	ly wakeup interrupt generation - X		
Reset generation (refer to the RCC section of the product reference manual for more details)	X		
Capability to work in system Stop			
Capability to work in system Standby		X	
Capability to generate an interrupt in system Stop	-	^	

4.7.7 Real-time clock (RTC)

The STM32U575/585 implement similar RTC features as STM32L4 and STM32L4+, adding some specification updates and enhancements. The main differences are stated in the table below.

Table 44. RTC features of STM32L4, STM32L4+ and STM32U575/585

Features	STM32L4/L4+	STM32U575/585
Binary mode with 32-bit free- running counter	N/A	X
RTC TrustZone support		

4.7.8 SysTick timer

The SysTick timer is dedicated to real-time operating systems but can also be used as a standard down-counter. The STM32U575/585 Cortex-M33 with TrustZone embeds two SysTick timers. When TrustZone is activated, the two SysTick timers are available, but when TrustZone is disabled, only one SysTick timer is available. STM32L4 and STML32L4+ embed a Cortex-M4 with just one SysTick timer.

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4.8 Signal/image processing accelerators

4.8.1 Digital filters

The STM32U575/585 embed two hardware digital filters, MDF and ADF, while STM32L4 and STM32L4+ include one DFSDM filter. Differences between the embedded filters are listed in the table below.

Table 45. Digital filters of STM32L4, STM32L4+ and STM32U575/585

Features	STM32L4/L4+	STM32U575/585		
Digital filter type	DFSDM	ADF	MDF	
Number of filters	Up to 8	1	6	
Input from internal ADC	X ⁽¹⁾ N/A		X	
Supported trigger sources	11/12 ⁽²⁾	2	14 ⁽³⁾	
Pulses skipper	X ⁽¹⁾	N/A		
Autonomous in Stop mode	N/A	X ⁽⁴⁾	X ⁽⁵⁾	

- 1. Not available for STM32L476/486xx.
- 2. LPTIM1 is the new trigger source for STM32L4+.
- 3. For available trigger sources, refer to the 'MDF/ADF trigger connections' tables in the reference manual.
- 4. Only Stop 0, Stop 1 and Stop 2 modes.
- 5. Only Stop 0 and Stop 1 modes.

4.8.2 CORDIC co-processor (CORDIC)

The CORDIC co-processor is a new peripheral embedded only in STM32U575/585 devices. It provides hardware acceleration of certain mathematical functions (mainly trigonometric ones) commonly used in motor control, metering, signal processing and many other applications.

The CORDIC speeds up the calculation of these functions compared to a software implementation, making possible the use of a lower operating frequency, or freeing up processor cycles in order to perform other tasks.

The cording main features are the following:

- 24-bit CORDIC rotation engine
- Circular and Hyperbolic modes
- Rotation and Vectoring modes
- Functions: sine, cosine, sinh, cosh, atan, atan2, atanh, modulus, square root, natural logarithm
- Programmable precision
- Low-latency AHB slave interface
- · Results readable as soon as ready, without polling or interrupt
- DMA read and write channels
- Multiple register read/write by DMA

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4.8.3 Filter math accelerator (FMAC)

The FMAC is only implemented on STM32U575/585. This peripheral performs arithmetic operations on vectors. It comprises a multiplier/accumulator (MAC) unit, together with address generation logic that allows FMAC to index vector elements held in local memory.

The FMAC main features are the following:

- 16 x 16-bit multiplier
- 24 + 2-bit accumulator with addition and subtraction
- 16-bit input and output data
- 256 x 16-bit local memory
- Up to 3 areas in memory for data buffers (two inputs, one output) can be defined by programmable base address pointers and associated size registers
- Circular input and output buffer
- Filter functions: FIR, IIR (direct form 1)
- Vector functions: dot product, convolution, correlation
- AHB slave interface
- DMA read and write data channels

4.8.4 Tough sensing controller (TSC)

The STM32U575/585, STM32L4 and STM32L4+ embed a touch sensing controller (TSC) with same features. The TSC provides a simple solution to add capacitive-sensing functionality to any application. A capacitive-sensing technology can detect a finger presence near an electrode that is protected from direct touch by a dielectric (such as glass or plastic). The capacitive variation introduced by the finger (or any conductive object) is measured using a proven implementation based on a surface charge transfer acquisition principle. Refer to the product reference manual for more details on TSC features.

The number of capacitive-sensing channels is dependent on the size of the package and subject to I/O availability. The TSC input/output signals and their pins mapping are partially compatible between STM32L4, STM32L4+ and STM32U575/585.

4.9 External memory interface peripherals

4.9.1 Octo-SPI interface (OCTOSPI)

The OCTOSPI peripheral provides a serial interface that enables communication with external serial memories such as Flash memory, PSRAM, HyperRAM $^{\text{TM}}$, HyperFlash $^{\text{TM}}$ and some specific ICs like FPGA or ASICs.

The Octo-SPI specialized communication interface targets single-, dual-, quad- or octal-SPI memories, and can be configured in three modes: Indirect, Status-polling and Memory-mapped.

The OCTOSPI I/O manager (OCTOSPIM) is a hardware peripheral that implements a low-level interface that enables:

- an efficient OCTOSPI pin assignment with a full I/O matrix (before alternate function map)
- a multiplex of single-, dual-, guad- and octal-SPI interfaces over the same bus

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The OCTOSPI peripheral is available on STM32L4+ and STM32U575/585, with several additional features.

Note:

The STM32L4 feature a QUADSPI peripheral (not an OCTOSPI). The OCTOSPI supports the same features as the QUADSPI, and additionally supports Octo-SPI memories.

Table 46. OCTOSPI features of STM32L4+ and STM32U575/585

Features	STM32L4+	STM32U575/585
Number of OCTOSPI instances		2
Octo-SPI I/O manager (OCTOSPIM)	Yes	
Single-ended clock for 3.0 V HyperBus [™] mode		es
Inverted clock for 1.8 V HyperBus mode		
Zero wait states like performance execution	N/A	
Support of AP Memory quad-SPI and Octal-SPI PSRAMs		
CS boundary and refresh Yes		Yes
Full support for HyperRAM memories Yes		
OTFDEC protecting Flash code	N1/A	
TrustZone security N/A		

4.9.2 Flexible static memory controller (FSMC)

The following table presents the FSMC interface differences between of STM32L4, STM32L4+ and STM32U575/585.

Note:

FSMC is not supported by STM32L41/42/43/44/45/46xxx.

Table 47. FSMC features of STM32L4, STM32L4+ and STM32U575/585

Features	STM32L4 STM32L4+		STM32U575/585
External memory interfaces	 SRAM NOR/NAND memories PSRAM NAND Flash memory with ECC hardware 	 SRAM NOR/NAND memories PSRAM NAND Flash memory with ECC hardware FRAM (ferroelectric RAM) 	SRAM NOR Flash memory/one NAND Flash memory PSRAM NAND Flash memory with ECC hardware FRAM (ferroelectric RAM)
Data bus width	8 or 16 bits		
New timing	N/A	NBL setup timingData hold timingClock divider ratio 1	New PSRAM counter timing

For STM32U575/585, FSMC registers can be configured as secure through the TZSC controller (refer to the reference manual for more details).

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5 Software migration

5.1 Reference documents

- Definitive guide to Cortex-M33 and Cortex-M4 processors
- STM32 Cortex-M4 MCUs and MPUs programming manual (PM0214)
- Cortex-M4 processor Technical Reference Manual
- Cortex-M33 processor Technical Reference Manual

5.2 Cortex-M4 and Cortex-M33 overview

5.2.1 STM32 Cortex-M4 processor and core peripherals

The Cortex-M4 processor is a high-performance 32-bit processor designed for the microcontroller market. It offers significant benefits to the developers, including:

- Outstanding processing performance combined with fast interrupt handling
- · Enhanced system debug with extensive breakpoint and trace capabilities
- Efficient processor core, system and memories
- Ultra-low power consumption with integrated sleep modes
- Platform security robustness, with integrated memory protection unit (MPU)

The Cortex-M4 processor is built on a high-performance processor core, with a 3-stage pipeline Harvard architecture, making it ideal for demanding embedded applications. The processor delivers an exceptional power efficiency through an efficient instruction set and extensively optimized design, providing high-end processing hardware including IEEE754- compliant single-precision floating-point computation, a range of single-cycle and SIMD multiplication and multiply-with-accumulate capabilities, a saturating arithmetic and dedicated hardware division.

The STM32 Cortex-M4 implementation is illustrated in the figure below.

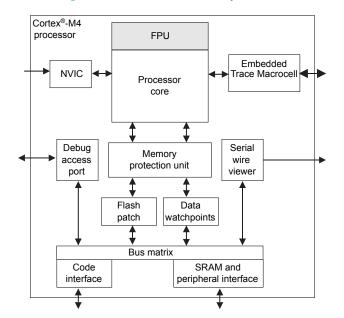


Figure 9. STM32 Cortex-M4 implementation

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Cortex-M4 key features

- Architecture 32 bits RISC Armv7E-M
- 3-stage pipeline with branch speculation
- Instruction set:
 - Thumb. Thumb-2
 - Hardware multiply, hardware divide, saturated arithmetic
 - DSP extensions:
 - Single-cycle 16/32-bit MAC
 - Single-cycle dual 16-bit MAC
 - 8/16-bit SIMD arithmetic
- FPU (VFPv4-SP)

5.2.2 STM32 Cortex-M33 processor and core peripherals

The Cortex-M33 processor is excellence in ultra-low-power, performance and security.

This processor is based on the Armv8-M architecture for use in environments requiring more security implementation. The Cortex-M33 core implements a full set of DSP (digital signal processing) instructions, TrustZone-aware support and a memory protection unit (MPU) that enhances the application security.

The Cortex-M33 core also features a single-precision floating-point unit (FPU), that supports all the Arm single precision data-processing instructions and all the data types.

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External PPB



STM32 Cortex-M33 implementation is illustrated in the figure below.

M-AHB interface Cortex-M33 Floating point processor MTB SRAM MTB unit (FPU) interface Coprocessor interface Nested vector CTI IRQ and interrupt power control Cross trigger Core controller interface interface (NVIC) ETM External IDAU-____**‡**____**‡**__ Memory protection interface -ATB instruction Security Data attribution unit Breakpoint watchpoint (SAU) unit (BPU)* and trace Secure memory Non-secure (DWT) memory protection protection unit (MPU_S) unit (MPU_NS) WIC Instrumentation Trace Macrocell Bus matrix D-AHB instrumentation (ITM) interface PPB bus Processor ROM table C-AHB S-AHB

interface

interface

Figure 10. STM32 Cortex-M33 implementation

Cortex-M33 key features are listed below:

- Arm-v8M architecture with 2/3 stage pipeline, Harvard, 1,4 DMIPS/MHz
- Single-cycle branch, no branch prediction
- · Hardware divide instruction
- Debug (CoreSight compliant)
- · Memory exclusive instructions
- NVIC without interrupts increased up to 480 max (256 priority levels)
- Enhanced MPU, more flexible (32 bytes) up to 16 regions (for each one of the secure and non-secure states)
- New AMBA[®] 5 AHB interface, support of security state extension to the system
- Support of external implementation defined attribution unit
- Fully compatible with TrustZone system

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^{*} Flash patching is not supported in the Cortex-M33 processor.



The differences between Cortex-M4 and Cortex-M33 are presented in the table below.

Table 48. Cortex-M4 versus Cortex-M33

Feature	Cortex-M4	Cortex-M33	
Instruction set architecture	Armv7-M	Armv8-M mainline	
instruction set architecture	Thumb,	Thumb-2	
Pipeline	Three	-stages	
Performance efficiency (CoreMark/MHz)	3.40	3.86	
DMIPS/MHz	1.25	1.50	
Memory protection	Y	es	
Maximum MPU regions	8	8 secure and 8 non-secure	
Trace (ETM or MTB)	ETMv3	MTB and/or ETMv4	
DSP	Yes		
Floating point hardware	T	es	
Bus protocol	AHB Lite, APB	AHB5	
Max. number of external interrupts	240	480	
CMSIS support	Y	es	
TrustZone for Armv8-M	No	Yes	
Coprocessor interface	No		

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5.2.3 Software point of view

The Cortex-M33 has the same features than the Cortex-M4, but includes also the following ones:

- Implementing Armv8-M architecture
- Implementing the latest floating point unit FPU specification (based on Arm FPv5 architecture) that adds more instructions than the Cortex-M4 has
- · AHB5 specification used for the system and memory interface, to extend security across the whole system
- Latest version of the memory protection unit (MPU) specification used to simply the setup of regions
- Extended number of maximum interrupts to 480
- Optional execution trace using MTB or ETM
- · Enhanced debug components to make simplify usage
- Coprocessor interface supporting up to 8 coprocessors units
- Hardware stack limit checking
- TrustZone security features adding efficient security features

The Cortex-M33 enhancements compared to Cortex-M4 are illustrated in the figure below.

Figure 11. Cortex-M33 enhancements versus Cortex-M4

TrustZone Stack limit checking New or enhanced versus Cortex-M4 **Enhanced debug** Coprocessor I/F **ETM** ETM/MTB **NVIC (maximum 240 IQR) NVIC (maximum 480 IQR)** MPU (PMSA v7) MPU (PMSA v8) AHB lite AHB5 FPU **FPU** SIMD/DSP SIMD/DSP WIC/SMD WIC/SMD Serial wire/JTAG Serial wire/JTAG Armv7-M Armv8-M mainline

Cortex-M33

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Cortex-M4



5.3 Cortex mapping overview

The mapping is different on the Cortex-M4 and the Cortex-M33 (see the table below).

Table 49. Cortex mapping for STM32L4, STM32L4+ and STM32U575/585

Feature		STM32L4 and STM32L4+	STM32U575/585	
	Architecture	Cortex-M4	Cortex-M33	
Core	NVIC	Maskable interrupt channel:	125 maskable interrupt channels (not including the 16 Cortex-M33 with FPU interrupt lines)	
	EXTI	 Up to 41 events/interrupts (STM32L4+ and STM32L49/4Axxx) Up to 40 events/interrupts (STM32L47/48xxx) Up to 37 events/interrupts (STM32L41/42/43/44/45/46xxx) 	23 events/interrupts	
	System timer	0xE000 E010 to 0xE000 E01F	0xE000 E010 to 0xE000 E0FF	
	NVIC	0xE000 E100 to 0xE000 E4EF	0xE000 E100 to 0xE000 ECFF	
Mapping	Floating point unit	0xE000 EF30 to 0xE000 EF44	0xE000 EF30 to 0xE000 EF44	
	MPU (memory protection unit)	0xE000 ED90 to 0xE000 EDB8	0xE000 ED90 to 0xE000 EDB8	

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6 Conclusion

This application note is a complement to the STM32L4, STM32L4+ and STM32U575/585 datasheets and reference manuals.

This document provides a simple guideline to migrate an existing product based on the STM32L4 Series and STM32L4+ Series to the STM32U575/585.

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Revision history

Table 50. Document revision history

Date	Version	Changes
20-Apr-2021	1	Initial release.

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